

# LP8868-Q1 Automotive Multi-Topology LED Driver with Inductive Fast Dimming

## 1 Features

- AEC-Q100 Qualified for automotive applications:
  - Temperature grade 1:  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ ,  $T_A$
- Integrated MOSFET for buck, buck-boost and boost topology
  - Wide input voltage: 4.5V to 65V
  - Integrated 5.2A and 150m $\Omega$  MOSFET
  - Switching frequency 100kHz to 2.2MHz
  - Spread spectrum for lower EMI
- High precision power FET dimming
  - Up to 4A output current in buck topology
  - Analog dimming (dimming ratio 256 :1)
  - Fast PWM dimming (150ns pulse width)
  - Hybrid and flexible dimming
- Full protection features:
  - Fault output
  - LED open and short protection
  - Cycle-by-cycle current limit
  - Switching FET failure protection
  - Thermal shutdown
  - Configurable thermal foldback curve

## 2 Applications

- Automotive infotainment
- Automotive instrument clusters
- Heads-up displays(HUD)
- Automotive lighting

## 3 Description

The LP8868-Q1 family is a non-synchronous multi-topology solution with 4.5V to 65V wide input range. By integrating the low-side NMOS switch, the device is capable of driving LEDs with high power density and high efficiency. The family also supports common cathode connection and single layer PCB design. The switching frequency is configurable from 100kHz to 2.2MHz with an optional spread spectrum feature for better EMI performance.

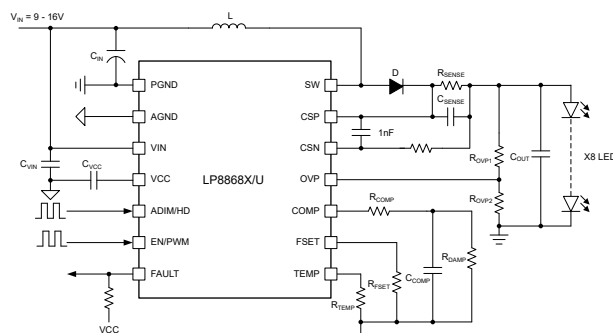
The LP8868-Q1 family supports four dimming options, including analog, PWM, hybrid and flexible dimming. Each dimming method can be configured through the PWM and ADIM input pins by means of simple high and low signals. The family adopts an adaptive off-time current mode control along with smart and accurate sampling to enable inductive fast dimming (IFD) and achieve high dimming accuracy.

The LP8868-Q1 family also provides multiple systematic protections, including LED open and short, sense resistor open and short, configurable thermal foldback and thermal shutdown. Fault output will send out acknowledge signals as soon as any fault condition is detected.

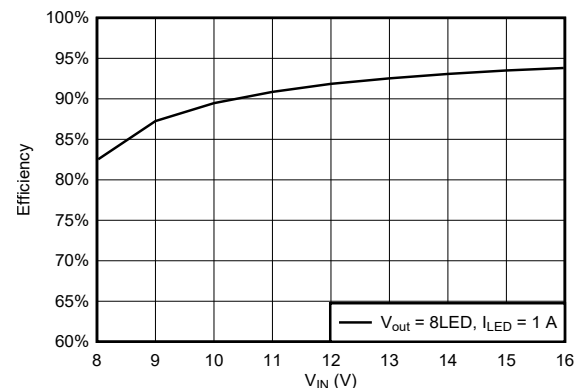
### Package Information

| PART NUMBER | PACKAGE <sup>(1)</sup> | PACKAGE SIZE <sup>(2)</sup> |
|-------------|------------------------|-----------------------------|
| LP8868-Q1   | VSON (14)              | 4.5mm x 3mm                 |
|             | HVSSOP (12)            | 4mm x 4.9mm                 |

- (1) For all available packages, see the orderable addendum at the end of the data sheet.
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.



Typical Boost LED Driver Application Schematic



Efficiency VS Input Voltage



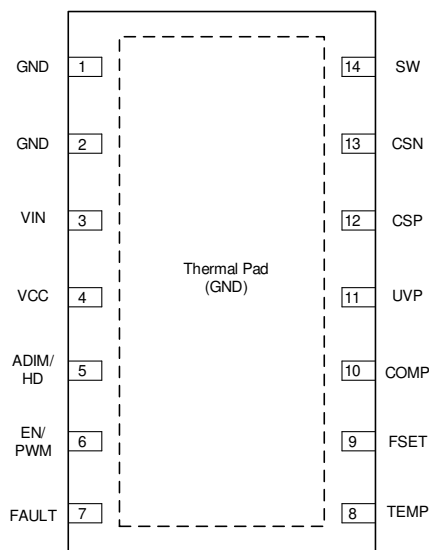
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## 4 Comparison Table

| Part Number    | Topology   | MOSFET Current Limit (Typical) | Spread Spectrum | Package |
|----------------|------------|--------------------------------|-----------------|---------|
| LP8868XQDMTRQ1 | Boost      | 6A                             | Enabled         | VSON    |
| LP8868YQDMTRQ1 | Buck-boost | 6A                             | Enabled         | VSON    |
| LP8868ZQDMTRQ1 | Buck       | 6A                             | Enabled         | VSON    |
| LP8868UQDMTRQ1 | Boost      | 6A                             | Disabled        | VSON    |
| LP8868VQDMTRQ1 | Buck-boost | 6A                             | Disabled        | VSON    |
| LP8868WQDMTRQ1 | Buck       | 6A                             | Disabled        | VSON    |
| LP8868XQDGNRQ1 | Boost      | 6A                             | Enabled         | HVSSOP  |
| LP8868YQDGNRQ1 | Buck-boost | 6A                             | Enabled         | HVSSOP  |
| LP8868ZQDGNRQ1 | Buck       | 6A                             | Enabled         | HVSSOP  |

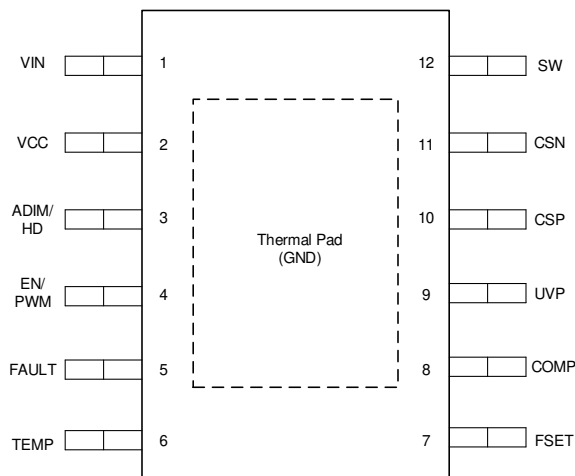
## 5 Pin Configuration and Functions



**Figure 5-1. 14-Pin Buck VSON (Top View)**

**Table 5-1. VSON Pin Functions for buck topology**

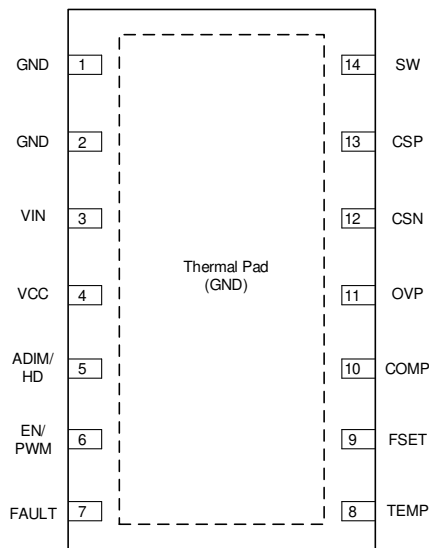
| PIN |             | TYPE <sup>(1)</sup> | DESCRIPTION                                                                                                                              |
|-----|-------------|---------------------|------------------------------------------------------------------------------------------------------------------------------------------|
| No. | NAME        |                     |                                                                                                                                          |
| 1   | PGND        | G                   | Power ground pin.                                                                                                                        |
| 2   | AGND        | G                   | Analog ground pin.                                                                                                                       |
| 3   | VIN         | P                   | Input power pin.                                                                                                                         |
| 4   | VCC         | P                   | Internal LDO output pin. Connect with a 10V, 1μF capacitor to GND.                                                                       |
| 5   | ADIM/HD     | I                   | Analog dimming or hybrid dimming pin. Pull high for PWM dimming only, pull low for hybrid dimming, input PWM signal for analog dimming.  |
| 6   | PWM/EN      | I                   | PWM dimming or EN pin. Pull high for always on, pull low for disabling the device, input PWM signal for PWM dimming.                     |
| 7   | FAULT       | O                   | Open drain output. Pull low when fault is detected.                                                                                      |
| 8   | TEMP        | I/O                 | Thermal foldback pin. Put different resistor values to GND to set different thermal foldback behavior curves.                            |
| 9   | FSET        | I/O                 | Switching frequency set pin, with range from 100kHz to 2.2MHz. Put different resistor values to GND for different switching frequencies. |
| 10  | COMP        | I/O                 | Error-amplifier output. Connect capacitors to GND. Different capacitor values determine different soft start times and bandwidths.       |
| 11  | UVP         | I                   | Undervoltage detection pin. Put different resistor dividers to set the LED open detection thresholds.                                    |
| 12  | CSP         | I                   | LED current sense positive pin.                                                                                                          |
| 13  | CSN         | I                   | LED current sense negative pin.                                                                                                          |
| 14  | SW          | P                   | Switching node pin. Internally connected to the low-side MOSFET. Connect with the power inductor and the Schottky diode.                 |
| Pad | Thermal Pad | G                   | Power ground pin.                                                                                                                        |



**Figure 5-2. 12-Pin Buck HVSSOP (Top View)**

**Table 5-2. HVSSOP Pin Functions for buck topology**

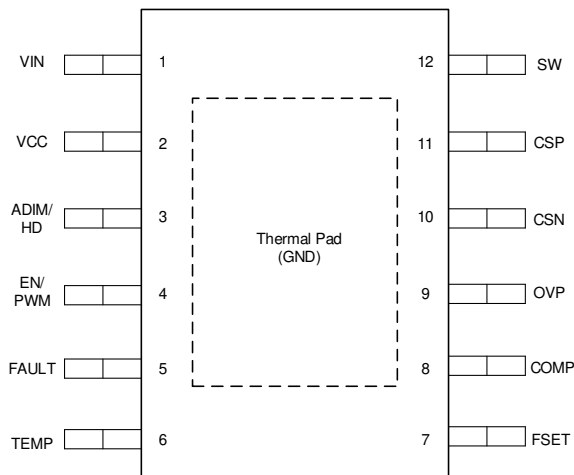
| PIN |             | TYPE <sup>(1)</sup> | DESCRIPTION                                                                                                                              |
|-----|-------------|---------------------|------------------------------------------------------------------------------------------------------------------------------------------|
| No. | NAME        |                     |                                                                                                                                          |
| 1   | VIN         | P                   | Input power pin.                                                                                                                         |
| 2   | VCC         | P                   | Internal LDO output pin. Connect with a 10V, 1μF capacitor to GND.                                                                       |
| 3   | ADIM/HD     | I                   | Analog dimming or hybrid dimming pin. Pull high for PWM dimming only, pull low for hybrid dimming, input PWM signal for analog dimming.  |
| 4   | PWM/EN      | I                   | PWM dimming or EN pin. Pull high for always on, pull low for disabling the device, input PWM signal for PWM dimming.                     |
| 5   | FAULT       | O                   | Open drain output. Pull low when fault is detected.                                                                                      |
| 6   | TEMP        | I/O                 | Thermal foldback pin. Put different resistor values to GND to set different thermal foldback behavior curves.                            |
| 7   | FSET        | I/O                 | Switching frequency set pin, with range from 100kHz to 2.2MHz. Put different resistor values to GND for different switching frequencies. |
| 8   | COMP        | I/O                 | Error-amplifier output. Connect capacitors to GND. Different capacitor values determine different soft start times and bandwidths.       |
| 9   | UVP         | I                   | Undervoltage detection pin. Put different resistor dividers to set the LED open detection thresholds.                                    |
| 10  | CSP         | I                   | LED current sense positive pin.                                                                                                          |
| 11  | CSN         | I                   | LED current sense negative pin.                                                                                                          |
| 12  | SW          | P                   | Switching node pin. Internally connected to the low-side MOSFET. Connect with the power inductor and the schottky diode.                 |
| Pad | Thermal Pad | G                   | Power ground pin and analog ground pin                                                                                                   |



**Figure 5-3. 14-Pin Boost/Buck-Boost VSON Top View**

**Table 5-3. VSON Pin Functions for boost/buck-boost topology**

| PIN |             | TYPE <sup>(1)</sup> | DESCRIPTION                                                                                                                              |
|-----|-------------|---------------------|------------------------------------------------------------------------------------------------------------------------------------------|
| No. | NAME        |                     |                                                                                                                                          |
| 1   | PGND        | G                   | Power ground pin.                                                                                                                        |
| 2   | AGND        | G                   | Analog ground pin.                                                                                                                       |
| 3   | VIN         | P                   | Input power pin.                                                                                                                         |
| 4   | VCC         | P                   | Internal LDO output pin. Connect with a 10V, 1μF capacitor to GND.                                                                       |
| 5   | ADIM/HD     | I                   | Analog dimming or hybrid dimming pin. Pull high for PWM dimming only, pull low for hybrid dimming, input PWM signal for analog dimming.  |
| 6   | PWM/EN      | I                   | PWM dimming or EN pin. Pull high for always on, pull low for disabling the device, input PWM signal for PWM dimming.                     |
| 7   | FAULT       | O                   | Open drain output. Pull low when fault is detected.                                                                                      |
| 8   | TEMP        | I/O                 | Thermal foldback pin. Put different resistor values to GND to set different thermal foldback behavior curves.                            |
| 9   | FSET        | I/O                 | Switching frequency set pin, with range from 100kHz to 2.2MHz. Put different resistor values to GND for different switching frequencies. |
| 10  | COMP        | I/O                 | Error-amplifier output. Connect capacitors to GND. Different capacitor values determine different soft start times and bandwidths.       |
| 11  | OVP         | I                   | Overvoltage detection pin. Put different resistor dividers to set the LED open detection thresholds.                                     |
| 12  | CSN         | I                   | LED current sense negative pin.                                                                                                          |
| 13  | CSP         | I                   | LED current sense positive pin.                                                                                                          |
| 14  | SW          | P                   | Switching node pin. Internally connected to the low-side MOSFET. Connect with the power inductor and the Schottky diode.                 |
| Pad | Thermal Pad | G                   | Power ground pin.                                                                                                                        |



**Figure 5-4. 12-Pin Boost/Buck-Boost HVSSOP Top View**

**Table 5-4. VSON Pin Functions for boost/buck-boost topology**

| PIN          |             | TYPE <sup>(1)</sup> | DESCRIPTION                                                                                                                              |
|--------------|-------------|---------------------|------------------------------------------------------------------------------------------------------------------------------------------|
| VSON Package | NAME        |                     |                                                                                                                                          |
| 1            | VIN         | P                   | Input power pin.                                                                                                                         |
| 2            | VCC         | P                   | Internal LDO output pin. Connect with a 10V, 1μF capacitor to GND.                                                                       |
| 3            | ADIM/HD     | I                   | Analog dimming or hybrid dimming pin. Pull high for PWM dimming only, pull low for hybrid dimming, input PWM signal for analog dimming.  |
| 4            | PWM/EN      | I                   | PWM dimming or EN pin. Pull high for always on, pull low for disabling the device, input PWM signal for PWM dimming.                     |
| 5            | FAULT       | O                   | Open drain output. Pull low when fault is detected.                                                                                      |
| 6            | TEMP        | I/O                 | Thermal foldback pin. Put different resistor values to GND to set different thermal foldback behavior curves.                            |
| 7            | FSET        | I/O                 | Switching frequency set pin, with range from 100kHz to 2.2MHz. Put different resistor values to GND for different switching frequencies. |
| 8            | COMP        | I/O                 | Error-amplifier output. Connect capacitors to GND. Different capacitor values determine different soft start times and bandwidths.       |
| 9            | OVP         | I                   | Overvoltage detection pin. Put different resistor dividers to set the LED open detection thresholds.                                     |
| 10           | CSN         | I                   | LED current sense negative pin.                                                                                                          |
| 11           | CSP         | I                   | LED current sense positive pin.                                                                                                          |
| 12           | SW          | P                   | Switching node pin. Internally connected to the low-side MOSFET. Connect with the power inductor and the Schottky diode.                 |
| Pad          | Thermal Pad | G                   | Power ground pin and analog ground pin                                                                                                   |

(1) I = Input, O = Output, P = Supply, G = Ground

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating ambient temperature range (unless otherwise noted)<sup>(1)</sup>

|                                |                                               | MIN  | MAX | UNIT |
|--------------------------------|-----------------------------------------------|------|-----|------|
| Voltage on pins                | VIN, UVP, OVP, CSP, CSN, SW,                  | −0.3 | 65  | V    |
| Voltage on pins                | VCC, ADIM/HD, EN/PWM, FAULT, TEMP, FSET, COMP | −0.3 | 5.5 | V    |
| Operation junction temperature | T <sub>J</sub>                                | −40  | 150 | °C   |
| Storage temperature            | T <sub>stg</sub>                              | −65  | 150 | °C   |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 6.2 ESD Ratings

|                    |                         | VALUE                                                                          | UNIT  |
|--------------------|-------------------------|--------------------------------------------------------------------------------|-------|
| V <sub>(ESD)</sub> | Electrostatic discharge | Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>              | ±2000 |
|                    |                         | Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup> | ±500  |

- (1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.  
 (2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating ambient temperature range (unless otherwise noted)

|                                                |                                  | MIN | MAX | UNIT |
|------------------------------------------------|----------------------------------|-----|-----|------|
| Input voltage range                            | VIN                              | 4.5 | 63  | V    |
| Input voltage range                            | UVP, OVP, CSP, CSN               | 0   | 63  | V    |
| Input voltage range                            | VCC, ADIM/HD, EN/PWM, TEMP, FSET | 0   | 5   | V    |
| Output voltage range                           | SW                               | 0   | 63  | V    |
|                                                | FAULT, COMP                      | 0   | 5   | V    |
| Operating junction temperature, T <sub>J</sub> |                                  | −40 | 150 | °C   |

### 6.4 Thermal Information

| THERMAL METRIC <sup>(1)</sup> |                                              | Device  |         | UNIT |
|-------------------------------|----------------------------------------------|---------|---------|------|
|                               |                                              | HVSSOP  | SON     |      |
|                               |                                              | 12 PINS | 14 PINS |      |
| R <sub>θJA</sub>              | Junction-to-ambient thermal resistance       | 38.3    | 39.1    | °C/W |
| R <sub>θJC(top)</sub>         | Junction-to-case (top) thermal resistance    | 52.2    | 39.5    | °C/W |
| R <sub>θJB</sub>              | Junction-to-board thermal resistance         | 13.9    | 14.7    | °C/W |
| ψ <sub>JT</sub>               | Junction-to-top characterization parameter   | 1.9     | 0.9     | °C/W |
| ψ <sub>JB</sub>               | Junction-to-board characterization parameter | 13.9    | 14.7    | °C/W |

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).



## 6.5 Electrical Characteristics

The electrical ratings specified in this section apply to all specifications in this document, unless otherwise noted. These specifications are interpreted as conditions that do not degrade the device parametric or functional specifications for the life of the product containing it.  $T_A = -40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ ,  $V_{IN} = 4.5\text{ V}$  to  $60\text{ V}$ , (unless otherwise noted).

| PARAMETER                           |                                                                                             | TEST CONDITIONS                                                                                   | MIN      | TYP      | MAX      | UNIT            |
|-------------------------------------|---------------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------|----------|----------|----------|-----------------|
| <b>INPUT SUPPLY</b>                 |                                                                                             |                                                                                                   |          |          |          |                 |
| $V_{VIN\_UVLO}$                     | $V_{IN}$ undervoltage lockout                                                               | Rising $V_{IN}$                                                                                   | 3.0      | 3.2      | 3.4      | V               |
|                                     |                                                                                             | Falling $V_{IN}$                                                                                  | 2.8      | 3.0      | 3.2      | V               |
|                                     | Hysteresis                                                                                  |                                                                                                   |          | 0.2      |          | V               |
| $I_{SD}$                            | Shut down current from $V_{IN}$                                                             | $V_{IN} = 12\text{ V}$ , $V_{EN/PWM} = 0\text{ V}$                                                |          | 0.8      | 2.3      | $\mu\text{A}$   |
| $I_{OFF}$                           | PWM off current from $V_{IN}$                                                               | $V_{IN} = 12\text{ V}$ , $V_{EN/PWM} = 0\text{ V}$                                                |          | 2.5      |          | mA              |
| $I_{OP}$                            | Normal operating current                                                                    | 400-kHz switching frequency                                                                       |          | 4.6      |          | mA              |
| $I_{OP}$                            | Normal operating current                                                                    | 2.2-MHz switching frequency                                                                       |          | 10.0     |          | mA              |
| $V_{VCC}$                           | Internal LDO output voltage                                                                 | $I_{VCC} = 10\text{ mA}$                                                                          | 5.0      | 5.15     | 5.3      | V               |
| $I_{VCC\_LIM}$                      | Internal LDO output current limit                                                           |                                                                                                   | 38       | 47       | 56       | mA              |
| <b>DIMMING</b>                      |                                                                                             |                                                                                                   |          |          |          |                 |
| $V_{PWM\_L}$                        | Low-level input voltage                                                                     |                                                                                                   |          |          | 0.4      | V               |
| $V_{PWM\_H}$                        | High-level input voltage                                                                    |                                                                                                   | 1.2      |          |          | V               |
| $V_{ADIM\_L}$                       | Low-level input voltage                                                                     |                                                                                                   |          |          | 0.4      | V               |
| $V_{ADIM\_H}$                       | High-level input voltage                                                                    |                                                                                                   | 1.2      |          |          | V               |
| $t_{PWM\_OUT\_ON}$                  | PWM output minimum on time                                                                  |                                                                                                   |          |          | 150      | ns              |
| $t_{PWM\_IN\_ON}$                   | PWM input minimum on time                                                                   |                                                                                                   |          |          | 150      | ns              |
| $t_{PWM\_IN\_OFF}$                  | PWM input minimum off time to disable device                                                |                                                                                                   | 57       |          | 77       | ms              |
| $f_{ADIM}$                          | Analog Dimming input frequency                                                              | 6-bit ADIM resolution                                                                             | 0.1      |          | 156      | kHz             |
| $f_{ADIM}$                          | Analog Dimming input frequency                                                              | 8-bit ADIM resolution                                                                             | 0.1      |          | 39       | kHz             |
| <b>FAULT</b>                        |                                                                                             |                                                                                                   |          |          |          |                 |
| $V_{OL}$                            | Output level low                                                                            | $I = 3\text{ mA}$                                                                                 |          |          | 0.1      | V               |
| $I_{LEAKAGE}$                       | Output leakage current                                                                      | $V = 5\text{ V}$                                                                                  |          |          | 1        | $\mu\text{A}$   |
| <b>FEEDBACK AND ERROR AMPLIFIER</b> |                                                                                             |                                                                                                   |          |          |          |                 |
| $g_{M(ea)}$                         | Transconductance gain                                                                       | ADIM 100% duty cycle, $V_{CSP-CSN} = 200\text{ mV}$ , $V_{COMP} = 1.5\text{ V}$                   | 205      | 265      | 325      | $\mu\text{A/V}$ |
| $I_{COMP}$                          | Source/sink current                                                                         | ADIM 100% duty cycle, $V_{CSP-CSN} = 200\text{ mV} \pm 200\text{ mV}$ , $V_{COMP} = 1.5\text{ V}$ | $\pm 24$ | $\pm 40$ | $\pm 56$ | $\mu\text{A}$   |
| $V_{CSP-CSN}$                       | Current sense threshold                                                                     | ADIM 100% duty cycle                                                                              | 194      | 200      | 206      | mV              |
| $V_{CSP-CSN}$                       | Current sense threshold                                                                     | ADIM 12.5% duty cycle, compared with 100% duty cycle                                              | 11.875   | 12.5     | 13.125   | %               |
| $V_{CSP-CSN}$                       | Current sense threshold                                                                     | ADIM 1.17% duty cycle, compared with 100% duty cycle                                              | 0.82     | 1.17     | 1.52     | %               |
| $I_{LEAK\_CSP/N}$                   | CSP+CSN pin leakage current                                                                 | $V_{IN} = 60\text{ V}$ , $V_{EN/PWM} = 5\text{ V}$                                                | 22       |          | 31       | $\mu\text{A}$   |
| $I_{LEAK\_CSP/N}$                   | CSP+CSN pin leakage current                                                                 | $V_{IN} = 60\text{ V}$ , $V_{EN/PWM} = 0\text{ V}$                                                | 10       |          | 15       | $\mu\text{A}$   |
| <b>POWER STAGE</b>                  |                                                                                             |                                                                                                   |          |          |          |                 |
| $R_{DS(on)}$                        | Switching FET on resistance                                                                 | $V_{IN} \geq 5\text{ V}$                                                                          |          | 150      |          | m $\Omega$      |
| $t_{min\_ON}$                       | Switching FET minimum on time                                                               |                                                                                                   |          | 100      |          | ns              |
| $t_{min\_OFF}$                      | Switching FET minimum off time                                                              |                                                                                                   |          | 100      |          | ns              |
| $f_{SW}$                            | Switching FET frequency                                                                     |                                                                                                   | 0.1      |          | 2.2      | MHz             |
| <b>CURRENT LIMIT</b>                |                                                                                             |                                                                                                   |          |          |          |                 |
| $I_{LIM}$                           | Switching FET cycle-by-cycle current limit (LP8868X/LP8868Y/LP8868U/LP8868V)                |                                                                                                   | 5.8      | 6.5      | 7.6      | A               |
| $I_{LIM}$                           | Switching FET cycle-by-cycle current limit (LP8868Z/LP8868W)                                |                                                                                                   | 5.2      | 6        | 7        | A               |
| $I_{LIM}$                           | Switching FET cycle-by-cycle current limit (LP8868X/LP8868Y/LP8868U/LP8868V) HVSSOP package |                                                                                                   | 5.8      | 7        | 7.8      | A               |

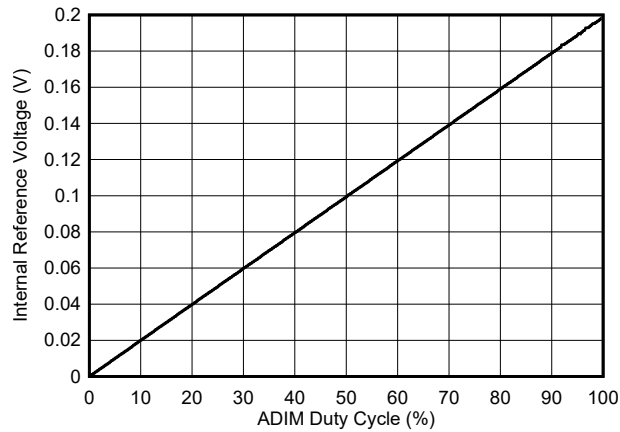
## 6.5 Electrical Characteristics (continued)

The electrical ratings specified in this section apply to all specifications in this document, unless otherwise noted. These specifications are interpreted as conditions that do not degrade the device parametric or functional specifications for the life of the product containing it.  $T_A = -40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ ,  $V_{IN} = 4.5\text{ V}$  to  $60\text{ V}$ , (unless otherwise noted).

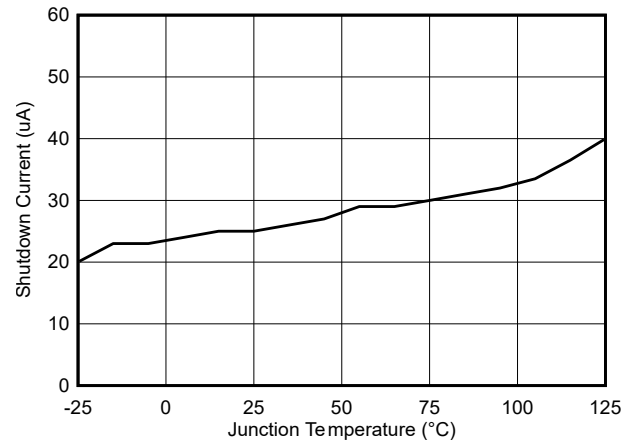
| PARAMETER                 |                                                                                | TEST CONDITIONS                | MIN | TYP | MAX | UNIT               |
|---------------------------|--------------------------------------------------------------------------------|--------------------------------|-----|-----|-----|--------------------|
| $I_{LIM}$                 | Switching FET cycle-by-cycle current limit<br>(LP8868Z/LP8868W) HVSSOP package |                                | 5.2 | 6.5 | 7.2 | A                  |
| <b>THERMAL PROTECTION</b> |                                                                                |                                |     |     |     |                    |
| $T_{th}$                  | Thermal foldback starting temperature threshold                                | $R_{TEMP} = 20\text{ k}\Omega$ |     | 130 |     | $^{\circ}\text{C}$ |
| $T_{TSD}$                 | Thermal shutdown temperature                                                   |                                |     | 165 |     | $^{\circ}\text{C}$ |
|                           | Hysteresis                                                                     |                                |     | 15  |     | $^{\circ}\text{C}$ |

## 6.6 Typical Characteristics

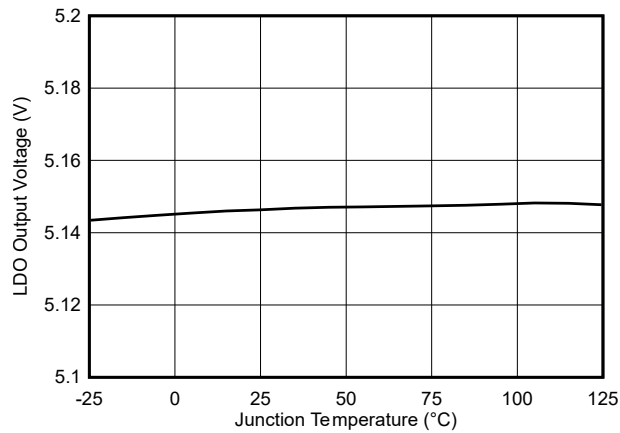
$V_{IN} = 12V$ ,  $L = 22\ \mu H$ ,  $F_{SW} = 400kHz$ , unless otherwise specified



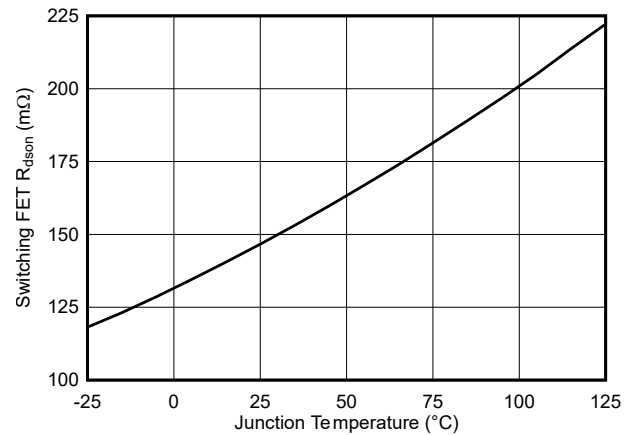
**Figure 6-1. ADIM Duty Cycle vs Reference Voltage in Analog Dimming**



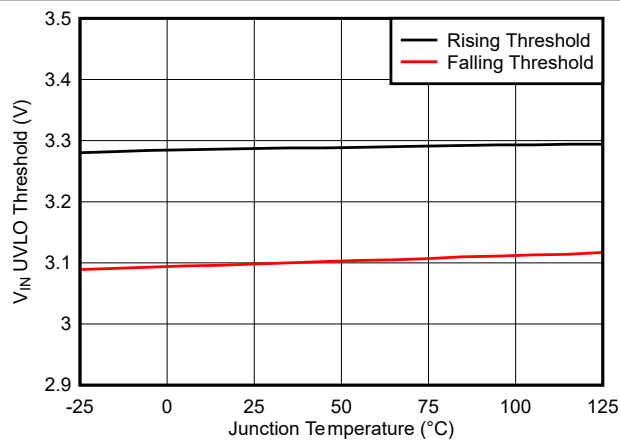
**Figure 6-2. Shutdown Current vs Junction Temperature**



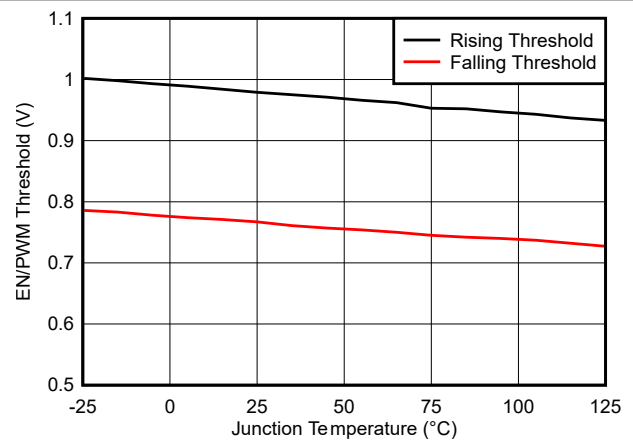
**Figure 6-3. Internal LDO Output vs Junction Temperature**



**Figure 6-4. Switching FET Rdson vs Junction Temperature**



**Figure 6-5. VIN UVLO Threshold vs Junction Temperature**



**Figure 6-6. EN/PWM Threshold vs Junction Temperature**

## 6.6 Typical Characteristics (continued)

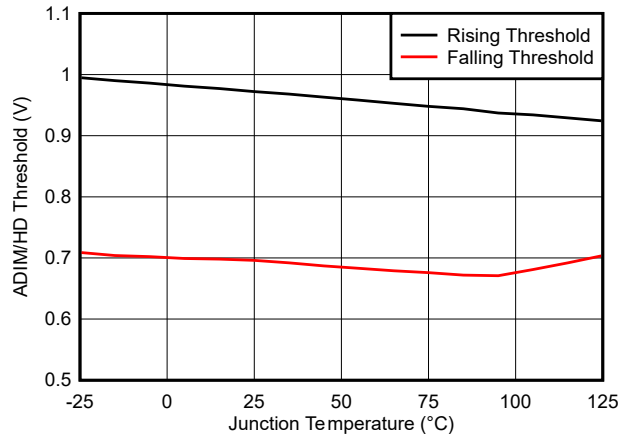


Figure 6-7. ADIM/HD Threshold vs Junction Temperature

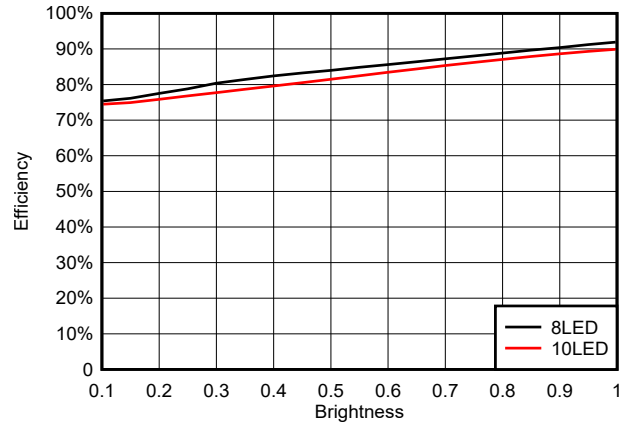


Figure 6-8. Efficiency at 1A Max Output Current with PWM Dimming, 22uH Inductor, Boost Topology

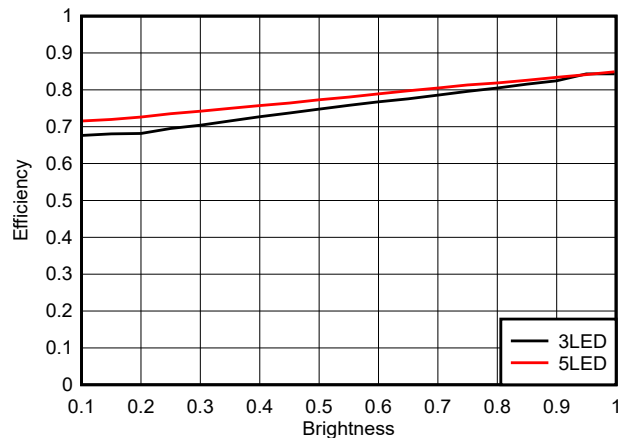


Figure 6-9. Efficiency at 1A Max Output Current with PWM Dimming, 22uH Inductor, Buck-Boost Topology

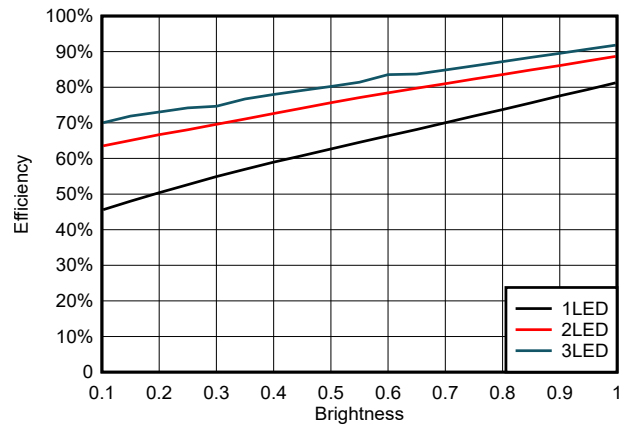


Figure 6-10. Efficiency at 3A Max Output Current with PWM Dimming, 22uH Inductor, Buck Topology

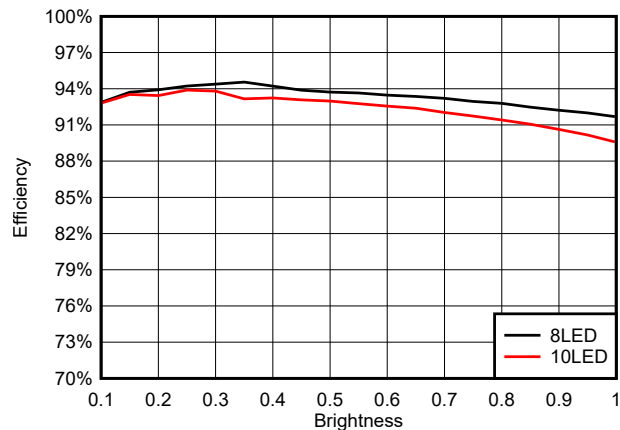


Figure 6-11. Efficiency at 1A Max Output Current with Analogy Dimming, 22uH Inductor, Boost Topology

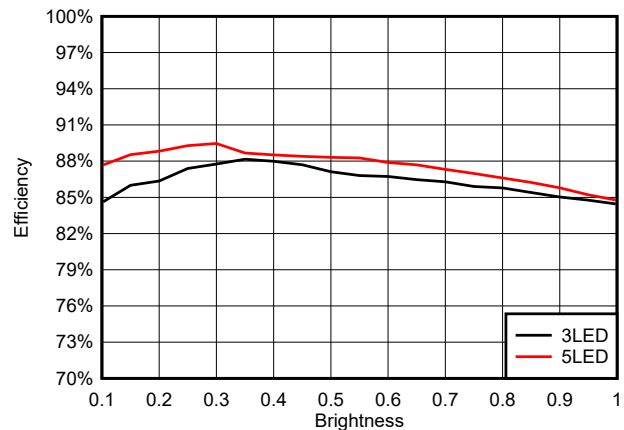


Figure 6-12. Efficiency at 1A Max Output Current with Analogy Dimming, 22uH Inductor, Buck-Boost Topology

## 6.6 Typical Characteristics (continued)

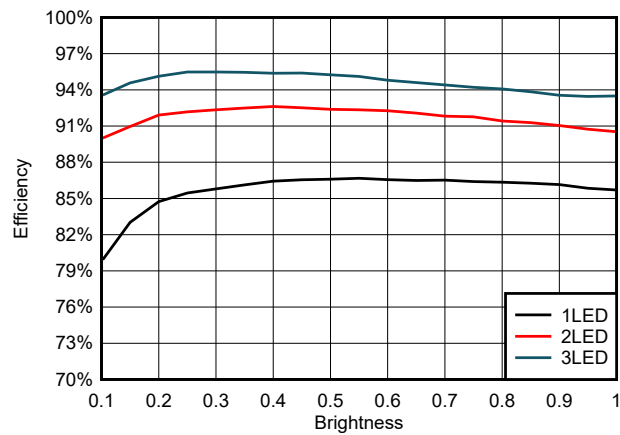


Figure 6-13. Efficiency at 3A Max Output Current with Analogy Dimming, 22uH Inductor, Buck Topology

## 7 Detailed Description

### 7.1 Overview

The LP8868-Q1 family is a 4A non-synchronous buck/boost/buck-boost LED drivers with 4.5V to 65V wide input range. By integrating the low-side NMOS switch with constant current and constant voltage controls, the device is capable of driving LEDs and charging batteries with high power density and high efficiency.

The switching frequency is configurable through the FSET pin, ranging from 100kHz to 2.2MHz, with optional spread spectrum feature to decrease the EMC emission and reduce the input filter size. The device supports four dimming options:

- Analog dimming
- PWM dimming
- Hybrid dimming
- Flexible dimming

Each dimming method is configurable through the PWM and ADIM input pins through simple high or low sequencing signals at start-up.

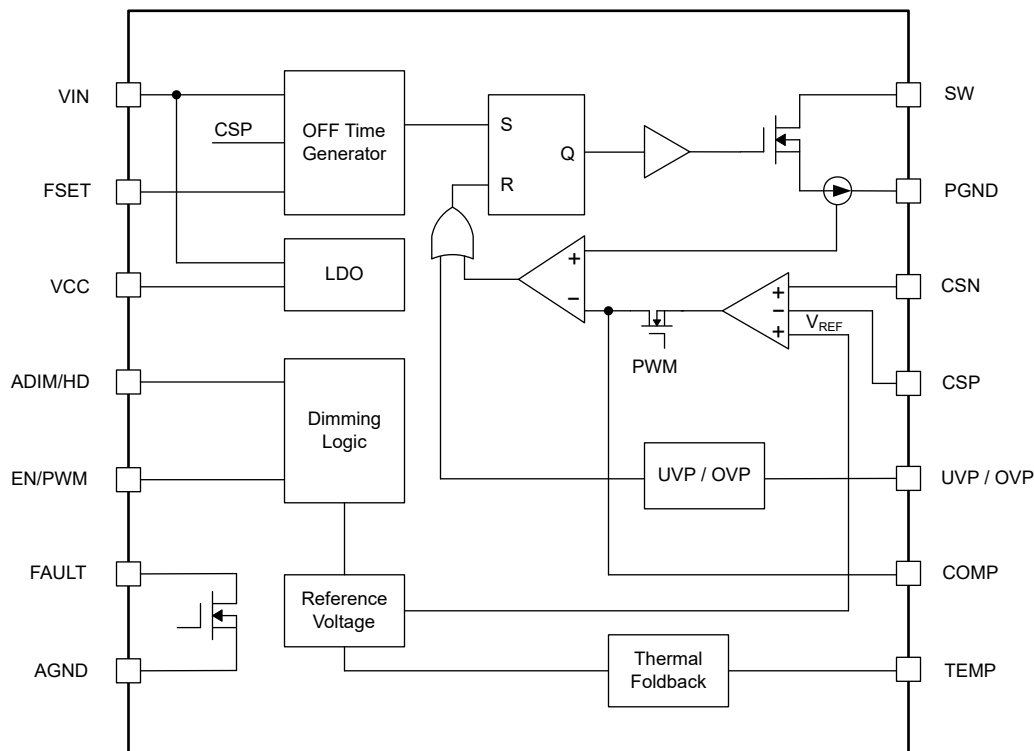
The device adopts an adaptive off-time current-mode control along with smart and accurate sampling to enable inductive fast dimming (IFD) and achieve high dimming ratio. The compensation bandwidth can be adjusted through an external capacitor on COMP pin based on system requirement.

The LP8868-Q1 family has extensive fault detection features:

- LED open and short detection
- Sense resistor open and short detection
- Configurable thermal foldback and thermal shutdown protection

The fault condition is indicated through the FAULT output pin.

### 7.2 Functional Block Diagram



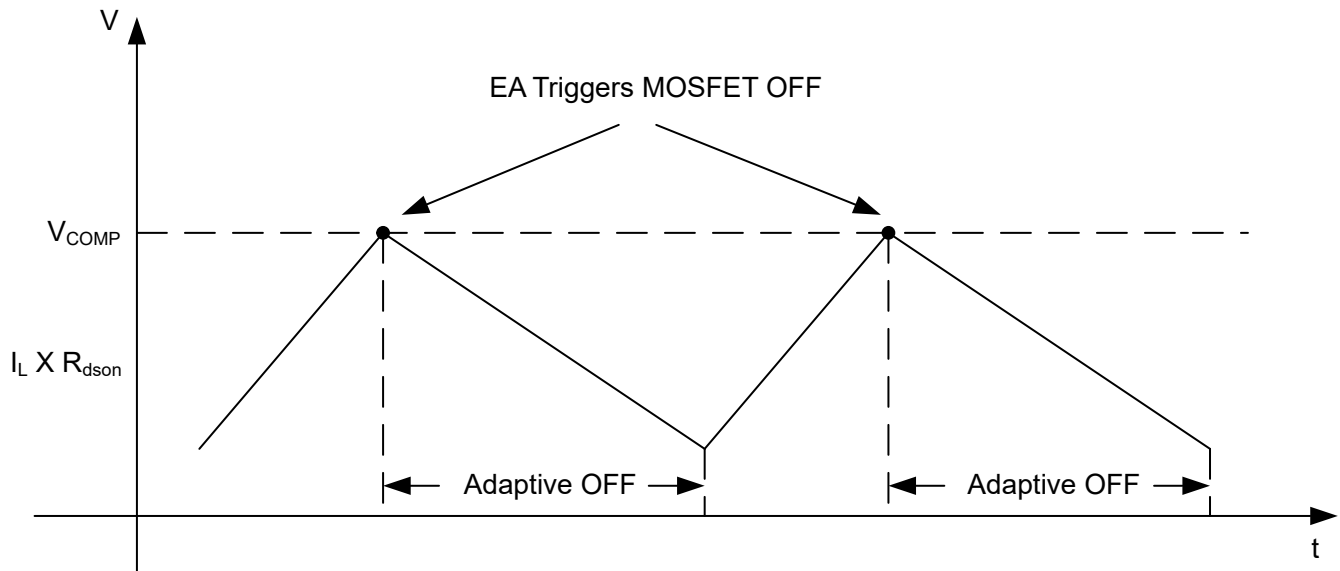
## 7.3 Feature Description

### 7.3.1 Adaptive Off-Time Current Mode Control

The LP8868-Q1 family adopts an adaptive off-time current-mode control to support fast transient response over a wide range of operation. The switching frequency is configurable through the FSET pin, ranging from 100kHz to 2.2MHz.

For average output current regulation, the sensed voltage across the sensing resistor between the CSP and CSN pins compares with the internal voltage reference,  $V_{REF}$ , through the error amplifier. The output of the error amplifier,  $V_{COMP}$ , passes through an external compensation network and compares with the peak current feedback at the PWM comparator

During each switching cycle, when the internal N-MOSFET is turned on, the peak current is sensed through the internal FET. When the sensed value of peak current reaches  $V_{COMP}$  at the input of PWM comparator, the N-MOSFET is turned off and the adaptive off-time counter starts counting. Once the adaptive off-time counter stops counting, the counter remains reset until when the N-MOSFET turns off. The counting off time is determined by the external resistor connected to the FSET pin and the input/output feed forward. Thus, the device maintains a nearly constant switching frequency at steady state and regulate the output average current at a desired value.



**Figure 7-1. Adaptive Off-time Current Mode Control Method**

#### 7.3.1.1 Switching Frequency Settings

The switching frequency of LP8868 family is adjustable from 100kHz to 2.2MHz through changing  $R_{FSET}$  connected between FSET pin and AGND. The default switching frequency is 100kHz when the FSET pin is connected to nothing.

The resistor value and the corresponding switching frequency are listed in [Table 7-1](#).

**Table 7-1. Switching Frequency versus  $R_{FSET}$  Resistor Value**

| Switching Frequency | Resistor Value (kΩ) |
|---------------------|---------------------|
| 100kHz              | 232                 |
| 200kHz              | 138                 |
| 300kHz              | 83                  |
| 400kHz              | 59                  |
| 600kHz              | 38                  |
| 800kHz              | 28                  |

**Table 7-1. Switching Frequency versus R<sub>FSET</sub> Resistor Value (continued)**

| Switching Frequency | Resistor Value (kΩ) |
|---------------------|---------------------|
| 1MHz                | 23                  |
| 1.2MHz              | 18                  |
| 1.5MHz              | 13                  |
| 1.8MHz              | 11                  |
| 2.2MHz              | 9                   |

For example, if R<sub>FSET</sub> is set to 59kΩ, the corresponding switching frequency is 400kHz.

In most cases, lower switching frequency has a higher system efficiency and better thermal performance.

#### 7.3.1.2 Spread Spectrum

The LP8868X/Y/Z-Q1 enables the spread spectrum feature (±7% from central frequency, 2kHz modulation frequency) which reduces EMI noise at the switching frequency and its harmonic frequencies.

Also, the LP8868U/V/W-Q1 disables the spread spectrum feature toward better brightness performance in low brightness scenario.

#### 7.3.2 Setting LED Current

The output current of the LED is controlled with external resistor R<sub>sense</sub> between CSP and CSN pins. Calculate the R<sub>sense</sub> value for the target current using equation Equation 1. To realize the IFD function and improve the accuracy of the output current in low duty cycle, the capacitor in parallel with sense resistor is required for boost and buck-boost topology. The capacitor in parallel with sense resistor is optional for buck topology. To avoid noise injection and increase robustness, a 100Ω resistor is recommended in the CSN pin.

$$R_{SENSE} = \frac{V_{REF}}{I_{LED\_FS}} \quad (1)$$

where

- V<sub>REF</sub> = 200mV
- R<sub>SENSE</sub> is current setting resistor (mΩ)
- I<sub>LED</sub> is output current (mA)

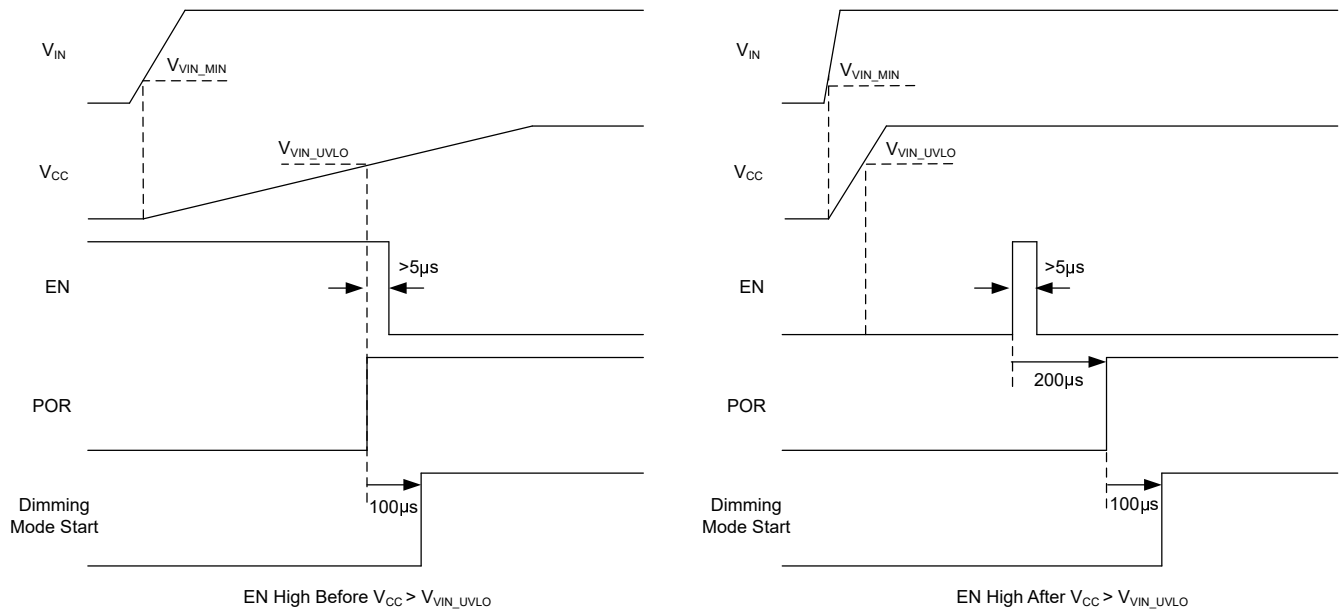
For example, if R<sub>sense</sub> is set to 100mΩ, I<sub>LED</sub> is calculated as 2A.

#### 7.3.3 Internal Soft Start

The LP8868-Q1 family implements the internal soft-start function. Once V<sub>IN</sub> rises above V<sub>VIN\_MIN</sub>, the internal LDO starts to charge V<sub>CC</sub> capacitor. If a 1μF capacitor is connected to the V<sub>CC</sub> pin, it takes approximately 800μs for V<sub>CC</sub> to rise above the V<sub>VIN\_UVLO</sub>. If EN/PWM pin is pulled high before V<sub>CC</sub> rises above V<sub>VIN\_UVLO</sub>, the POR enables directly after V<sub>CC</sub> is above V<sub>VIN\_UVLO</sub> and waits for 100μs to start dimming mode. EN/PWM pin remains high for more than 5μs after V<sub>CC</sub> rises above V<sub>VIN\_UVLO</sub>. If using 1μF V<sub>CC</sub> capacitor, the recommendation is to wait for 1ms prior to starting dimming mode after V<sub>IN</sub> rises above V<sub>VIN\_MIN</sub>.

If EN/PWM pin has the first PWM pulse appearing after V<sub>CC</sub> rises above V<sub>VIN\_UVLO</sub>, the device waits for 200μs to enable POR and another 100μs to begin dimming mode. Hence, without triggering V<sub>IN</sub> UVLO, the device can be re-enabled after disabled and wait for 300μs to start dimming mode. The initial enable PWM pulse lasting more than 5μs is required at EN/PWM input pin to enable the device. After dimming mode is started, the device enters four different dimming modes based on the configuration of ADIM/HD pin and EN/PWM pin.





**Figure 7-2. Start-up Sequence**

### 7.3.4 Dimming Mode

The LP8868 family has 4 optional dimming modes determined by the waveform in PWM and ADIM pins. The dimming mode is started either 1ms after  $V_{IN}$  exits UVLO or 300μs after renable by EN/PWM pin. The configuration to one of the four dimming modes are shown in the table below.

**Table 7-2. Dimming Mode Configuration**

| Dimming Mode     | EN/PWM Pin | ADIM/HD Pin |
|------------------|------------|-------------|
| PWM dimming      | PWM signal | High        |
| Analog dimming   | High       | PWM signal  |
| Hybrid dimming   | PWM signal | Low         |
| Flexible dimming | PWM signal | PWM signal  |

#### 7.3.4.1 PWM Dimming

The PWM dimming mode is enabled when the ADIM/HD input pin is always high and the PWM/EN input pin is configured by a PWM input signal. Device supports PWM input signals with ultra-narrow pulse width down to 200ns in PWM dimming mode. The input duty cycle can be changed in the opposite direction only when duty cycle changes by more than 0.38% in hybrid dimming.

In PWM dimming mode, when the PWM input signal at the PWM pin turns from low to high, the internal NMOS FET starts switching and the inductor current rises to the determined value. The LED current is then regulated at the determined value, as long as the PWM input signal remains high. When the PWM input signal turns from high to low, the internal FET is turned off, causing the inductor current to fall to zero. The internal FET remains off and the LED current remains at zero if the PWM input signal stays low.

#### 7.3.4.2 Analog Dimming

The LP8868 family supports analog dimming which regulates the LED current through the ADIM/HD pin. The analog dimming mode is enabled when the PWM/EN pin is always high and the ADIM/HD pin is configured by a PWM input signal. The internal digital circuits respond to the duty cycle change of the PWM input signal within a delay that lasts tens of micro-seconds.

The internal voltage reference,  $V_{REF}$ , changes in proportion to the duty cycle of the PWM input signal at the ADIM/HD pin. For example,  $V_{REF}$  is 200mV when the PWM input signal at the ADIM/HD pin has a 100% duty cycle. For example,  $V_{REF}$  is 20mV when the PWM input signal has a 10% duty cycle.

#### 7.3.4.3 Hybrid Dimming

The LP8868 family supports a unique hybrid dimming function to maximize the dimming performance, especially when both high dimming frequency and high dimming ratio are needed. The hybrid dimming mode is enabled when the ADIM/HD pin is always low and the PWM/EN pin is configured by a PWM input signal.

When the hybrid dimming is enabled, the LED current is regulated by the analog dimming at high brightness level (from 12.5% to 100%) and by the PWM dimming at low brightness level (from 0% to 12.5%). At a high brightness level, the internal voltage reference,  $V_{REF}$ , changes in proportion to the duty cycle of the PWM input signal at the PWM/EN pin. At a low brightness level,  $V_{REF}$  remains unchanged and an internal PWM generator is enabled. Thus, the LED is turned on and off corresponding to the on and off of the internal PWM signal of which the frequency and the duty cycle are configured by the PWM input signal at the PWM/EN pin. The detailed hybrid dimming behavior is illustrated in the below figure.

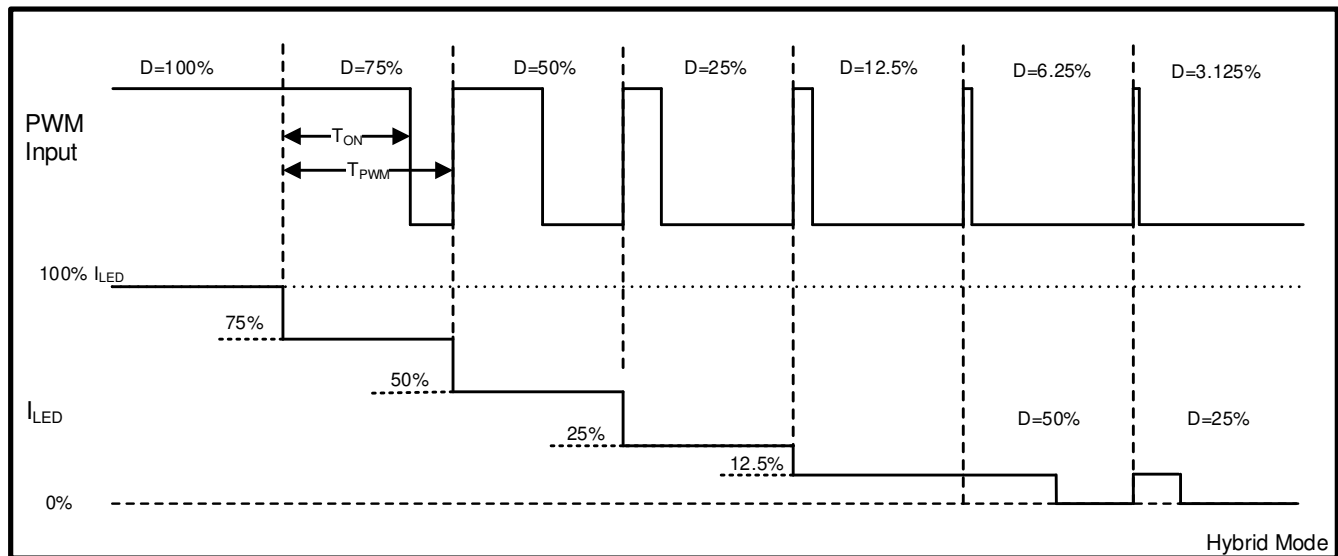


Figure 7-3. Hybrid Dimming

#### 7.3.4.4 Flexible Dimming

The LP8868 family also supports flexible dimming to maximize the flexibility of dimming control, in which the LED current value and the on/off behavior are independently controllable. The flexible dimming mode is enabled when both the ADIM/HD pin and the PWM/EN pin are configured by PWM input signals at the same time. Therefore, in flexible dimming mode, the LED is turned on and off corresponding to the on and off of the PWM input signal at the PWM/EN pin while the reference voltage changes in proportion to the duty cycle of the PWM input signal at the ADIM/HD pin.

#### 7.3.5 Undervoltage Lockout

The LP8868 family implements an internal undervoltage-lockout (UVLO) circuitry connecting to the VCC pin. The UVLO is triggered and then device is disabled when the VCC pin voltage falls below the internal UVLO threshold voltage,  $V_{VCC\_UVLO}$  typically 3.0V, with a typical 0.2V hysteresis. The VCC pin is the output of an internal regulator of which the input is supplied by the VIN pin. Therefore, if VIN pin voltage falls close to above the  $V_{VCC\_UVLO}$  (around 500mV above), the UVLO is triggered.

#### 7.3.6 Fault Protection

The LP8868 family provides fault protections and send fault report signals in many fault conditions, including:

- LED open
- LED short to GND
- Sense resistor open and short
- Internal switching FET fault

- Thermal shutdown

The fault criterion for different topology is listed below.

**Table 7-3. Protections in Buck Topology**

| TYPE                         | CRITERION                             | BEHAVIOR                                                                                                                                |
|------------------------------|---------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------|
| LED open load                | $V_{UVP} < 1.2V$ for 100us            | Fault pin pulls low. The device stops switching when $V_{UVP} < 1.2V$ .                                                                 |
| LED+ and LED- short circuit  | $V_{IN} - V_{CSP} < 300mV$ for 30ms   | Fault pin pulls low. The device keeps normal behavior.                                                                                  |
| LED- short to GND            | $V_{UVP} < 1.2V$ for 100us            | Fault pin pulls low. The device stops switching and recovers when fault is removed.                                                     |
| Sense-resistor open load     | $V_{CSP} - V_{CSN} > 300mV$ for 20us  | Fault pin pulls low. The device stops switching and recovers when fault is removed.                                                     |
| Sense-resistor short circuit | Error amplifier output high for 100us | Fault pin pulls low. The device keeps switching under the cycle-by-cycle current limit.                                                 |
| Switching FET open           | Error amplifier output high for 100us | Fault pin pulls low. The device keeps maximum duty cycle turn-on switching.                                                             |
| Switching FET short          | $V_{CSP} - V_{CSN} > 300mV$ for 20us  | Fault pin pulls low. The device stops switching and recovers when fault is removed.                                                     |
| Thermal shutdown             | $T_J > T_{TSD}$ for 100us             | Fault pin pulls low. The device stops switching when $T_J > T_{TSD}$ , and is re-activated when $T_J$ falls below the hysteresis level. |
| VIN UVLO                     | $V_{CC} < 3V$                         | Fault pin pulls low. The device stops switching and recovers when fault is removed.                                                     |

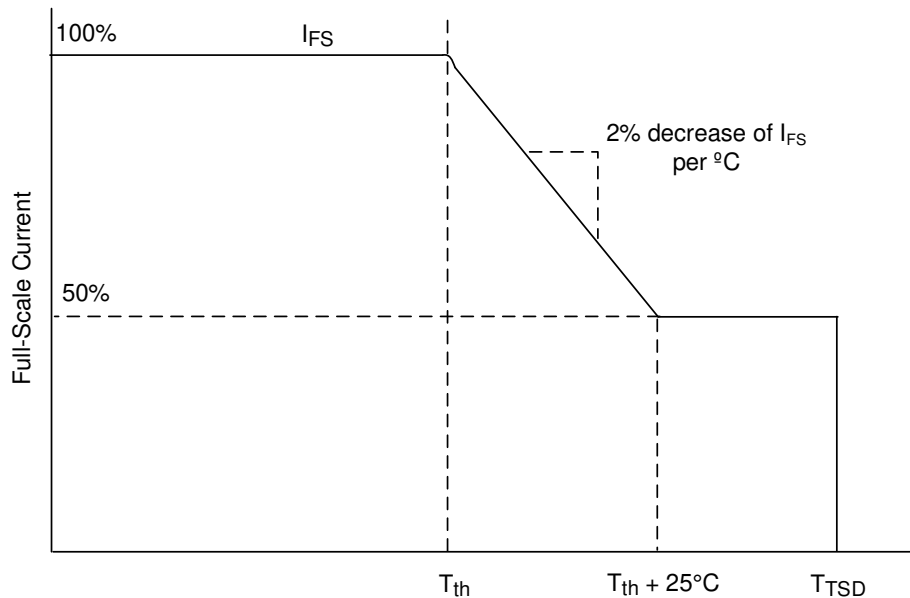
**Table 7-4. Protections in Boost / Buck-Boost topology**

| TYPE                                     | CRITERION                             | BEHAVIOR                                                                                                                                |
|------------------------------------------|---------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------|
| LED open load                            | $V_{OVP} > 1.2V$ for 100us            | Fault pin pulls low. The device stops switching when $V_{OVP} > 1.2V$ .                                                                 |
| LED+ and LED- short circuit (Buck-Boost) | $V_{CSP} - V_{IN} < 300mV$ for 30ms   | Fault pin pulls low. The device keeps normal behavior.                                                                                  |
| LED+ short to GND                        | $V_{CSP} - V_{CSN} > 300mV$ for 20us  | Fault pin pulls low. The device stops switching and recovers when fault is removed.                                                     |
| Sense-resistor open load                 | $V_{CSP} - V_{CSN} > 300mV$ for 20us  | Fault pin pulls low. The device stops switching and recovers when fault is removed.                                                     |
| Sense-resistor short circuit             | Error amplifier output high for 100us | Fault pin pulls low. The device keeps switching under the cycle-by-cycle current limit.                                                 |
| Switching FET open                       | Error amplifier output high for 100us | Fault pin pulls low. The device keeps maximum duty cycle turn-on switching.                                                             |
| Switching FET short                      | Error amplifier output high for 100us | Fault pin pulls low. The device tries to keep switching.                                                                                |
| Thermal shutdown                         | $T_J > T_{TSD}$ for 100us             | Fault pin pulls low. The device stops switching when $T_J > T_{TSD}$ , and is re-activated when $T_J$ falls below the hysteresis level. |
| VIN UVLO                                 | $V_{CC} < 3V$                         | Fault pin pulls low. The device stops switching and recovers when fault is removed.                                                     |

### 7.3.7 Thermal Foldback

The LP8868 family integrates thermal shutdown protection to prevent the device from overheating. To provide design margin of system thermal performance, the device enables a programmable thermal foldback function which automatically reduces the full-scale output current,  $I_{FS}$ , at high junction temperature. When the device, along with the LEDs, are mounted on the same thermal substrate, the thermal performance is effectively improved due to the reduction of dissipation need for both and LED.

As the junction temperature rises above the thermal foldback threshold temperature,  $T_{th}$ , the full-scale current starts to reduce following the current-temperature curve shown in the below figure. The current starts to reduce from the 100% level, typically at a rate of 2% of  $I_{FS}$  per  $^{\circ}C$  until the current drops to 50% of the full scale. Once the junction temperature rises  $25^{\circ}C$  above the  $T_{th}$ , the current continues to decrease at a lower rate until the temperature reaches above the overtemperature shutdown threshold temperature,  $T_{TSD}$ .



**Figure 7-4. Thermal Foldback**

The  $T_{th}$  can be adjusted by changing the resistor  $R_{TEMP}$  which connects between the TEMP and GND pin. The  $T_{th}$  and the corresponding  $R_{TEMP}$  value are listed in below table.

**Table 7-5.  $T_{th}$  versus  $R_{TEMP}$  Resistor Value**

| $T_{th}$ ( $^{\circ}C$ ) | Resistor Value (k $\Omega$ ) |
|--------------------------|------------------------------|
| 80                       | 200                          |
| 90                       | 100                          |
| 100                      | 60                           |
| 110                      | 40                           |
| 120                      | 28                           |
| 130                      | 20                           |
| 140                      | 15                           |
| 150                      | 10                           |



## 8.2.1.2 Detailed Design Procedure

### 8.2.1.2.1 Inductor Selection

For this design, the input voltage is 9V to 16V. The output is 8 white LEDs in series and the inductor current ripple by requirement is less than 40% of maximum LED current. To choose a proper peak-to-peak inductor current ripple, do not violate the low-side FET current limit when the converter works in no-load condition. Avoiding violation requires half of the peak-to-peak inductor current ripple to be lower than that limit. Another consideration is to confirm reasonable inductor core loss and copper loss caused by the peak-to-peak current ripple. Once the peak-to-peak inductor current ripple is chosen, use [Equation 2](#) to calculate the recommended value of the inductor L.

$$L = \frac{V_{IN(min)} \times (V_{OUT} - V_{IN(min)})}{V_{OUT} \times K_{IND} \times I_{L(max)} \times f_{SW}} \quad (2)$$

where

- $K_{IND}$  is a coefficient that represents the amount of inductor ripple current relative to the maximum LED current
- $I_{L(max)}$  is the maximum average inductor current
- $f_{SW}$  is the switching frequency
- $V_{IN(min)}$  is the minimum input voltage
- $V_{OUT}$  is the sum of the voltage across LED load and the voltage across sense resistor

With the chosen inductor value, calculate the actual inductor current ripple using [Equation 3](#).

$$I_{L(ripple)} = \frac{V_{IN(min)} \times (V_{OUT} - V_{IN(min)})}{V_{OUT} \times L \times f_{SW}} \quad (3)$$

Verify that the design ratings of inductor RMS current and saturation current are greater than the ratings in the system requirement. Perform this verification to establish that there is no inductor overheat or saturation occurring. During power up, transient conditions or fault conditions, the inductor current may exceed the normal operating current and reach the current limit. Therefore, the preference is to select a saturation current rating equal to or greater than the converter current limit. The peak-inductor-current and RMS current equations are shown in [Equation 4](#) and [Equation 5](#).

$$I_{L(peak)} = I_{L(max)} + \frac{I_{L(ripple)}}{2} \quad (4)$$

$$I_{L(rms)} = \sqrt{I_{L(max)}^2 + \frac{I_{L(ripple)}^2}{2}} \quad (5)$$

In this design,  $V_{IN(min)} = 9V$ ,  $V_{OUT} = 24V$ ,  $I_{LED} = 1A$ , considering the efficiency as 0.9,  $I_{L(max)} = 2.96A$ ,  $f_{SW} = 400kHz$ , choose  $K_{IND} = 0.4$ , the calculated inductance is 11.9μH. A 10μH inductor is chosen. With this inductor, the ripple, peak, and rms currents of the inductor are 1.41A, 3.67A, 2.96A, respectively.

### 8.2.1.2.2 Input Capacitor Selection

An input capacitor is required to reduce the surge current drawn from the input supply and the switching noise coming from the device. Electrolytic capacitors are recommended for energy storage. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of the low ESR and small temperature coefficients. For most applications, the recommendation is to place a 10μF ceramic capacitor along with a 0.1μF capacitor from VIN to PGND/AGND to provide high-frequency filtering. Verify that the input capacitor voltage rating is greater than the maximum input voltage. Use [Equation 6](#) to calculate the input ripple voltage, where  $ESR_{CIN}$  is the ESR of input capacitor, and  $K_{DR}$  is the derating coefficient of ceramic capacitance at the applied DC voltage.

$$V_{IN(ripple)} = \frac{I_{L(ripple)}}{8 \times K_{DR} \times C_{IN} \times f_{SW}} \quad (6)$$

In this design, a 33μF, 100V electrolytic capacitor, 10μF, 100V X7R ceramic capacitor and 0.1μF, 100V X7R ceramic capacitor are chosen, yielding approximately 88mV input ripple voltage.

#### 8.2.1.2.3 Output Capacitor Selection

The output capacitor reduces the high-frequency current ripple through the LED string. Excessive current ripple increases the RMS current in the LED string, therefore increasing the LED temperature.

1. Calculate the total dynamic resistance of the LED string ( $R_{LED}$ ) using the LED manufacturer data sheet.
2. Calculate the required impedance of the output capacitor ( $Z_{OUT}$ ) given the acceptable peak-to-peak ripple current through the LED string,  $I_{LED(ripple)}$ .  $I_{L(ripple)}$  is the peak-to-peak inductor ripple current as calculated with the selected inductor.
3. Calculate the minimum effective output capacitance required.
4. Increase the output capacitance appropriately due to the derating effect of applied DC voltage.

See [Equation 7](#), [Equation 8](#), and [Equation 9](#).

$$R_{LED} = \frac{\Delta V_F}{\Delta I_F} \times \# \text{ of LEDs} \quad (7)$$

$$Z_{COUT} = \frac{R_{LED} \times I_{LED(ripple)}}{I_{L(max)} - I_{LED(ripple)}} \quad (8)$$

$$C_{COUT} = \frac{1}{2\pi \times f_{SW} \times Z_{COUT}} \quad (9)$$

Once the output capacitor is chosen, use [Equation 10](#) to estimate the peak-to-peak ripple current through the LED string.

$$I_{LED(ripple)} = \frac{Z_{COUT} \times I_{L(ripple)}}{Z_{COUT} + R_{LED}} \quad (10)$$

Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of the low ESR and small temperature coefficients. In this design, a 10μF, 50V X7R ceramic capacitor is chosen.

#### 8.2.1.2.4 Sense Resistor Selection

The maximum LED current is 1A at 100% PWM duty and the corresponding  $V_{REF}$  is 200mV. Use [Equation 11](#) to calculate the sense resistance as 200mΩ. Note that the power consumption of the sense resistor is 200mW, requiring enough margin of the resistor's power rating in selection.

$$R_{SENSE} = \frac{V_{REF}}{I_{LED\_FS}} \quad (11)$$

In boost topology,  $C_{SENSE}$  is required to achieve the IFD control. Using [Equation 12](#), a 10μF, 50V X7R ceramic capacitor is chosen for  $C_{SENSE}$  to suppress the ac magnitude of sense feedback less than 200mV. A 100Ω resistor is recommended at CSN pin to avoid noise injection and increase robustness.

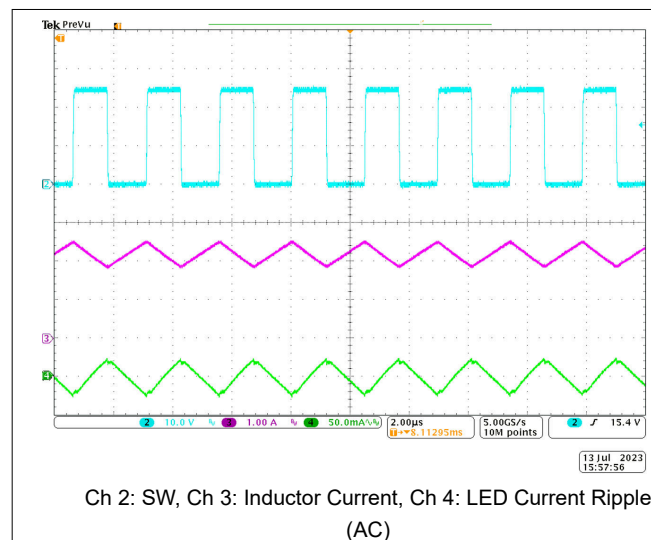
$$C_{SENSE} = \frac{0.25 \times I_{L(max)}}{200mV \times f_{SW}} \quad (12)$$

#### 8.2.1.2.5 Other External Components Selection

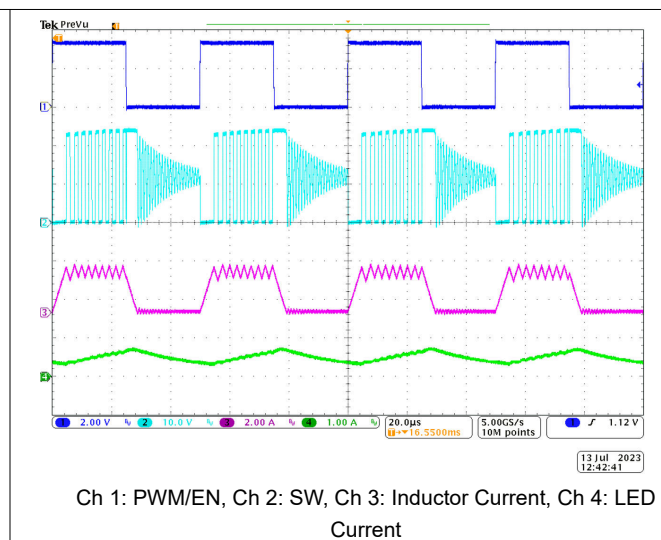
In this design, a 0.1μF, 50V X7R ceramic capacitor is chosen for high-frequency filtering of sense feedback.

For loop stability, the recommendation is to select a 1nF, 10V X7R ceramic capacitor for  $C_{COMP}$  and a 1kΩ resistor for  $R_{COMP}$ . A 1MΩ resistor is chosen for  $R_{DAMP}$  to suppress the overshoot current at rising edge of PWM on.

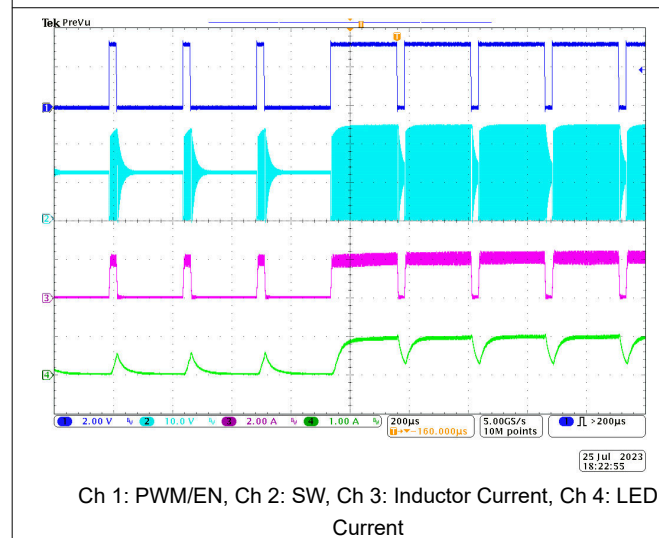
### 8.2.1.3 Application Curves



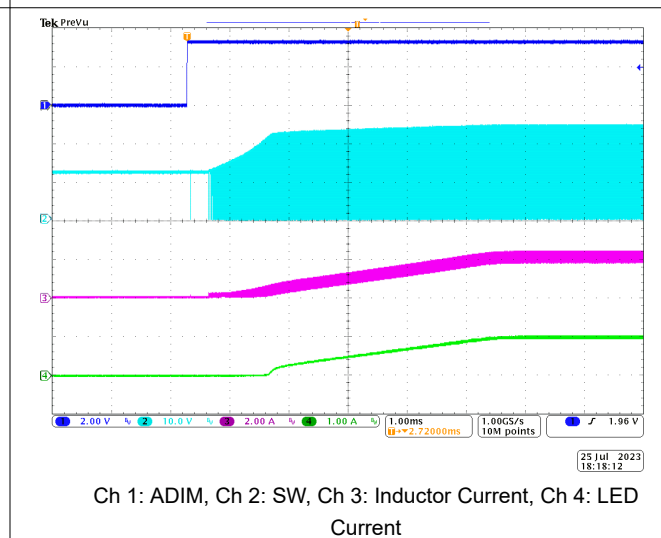
**Figure 8-2. LED Current Ripple at ADIM = 100%, 1kHz and  $F_{SW} = 400\text{kHz}$**



**Figure 8-3. LED Current Ripple at PWM = 50%, 20kHz and  $F_{SW} = 400\text{kHz}$**

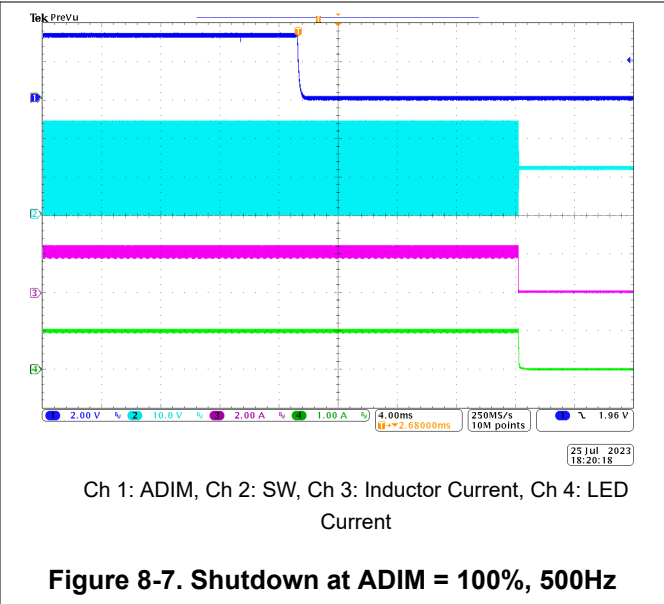
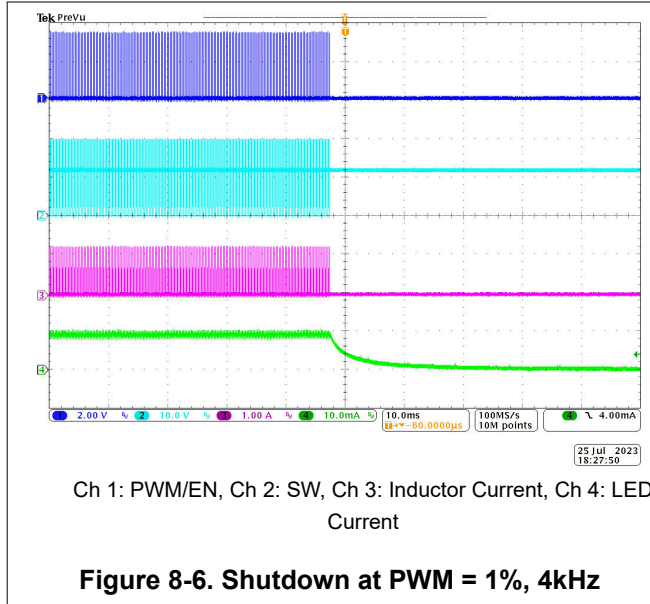


**Figure 8-4. LED Current Transient for a PWM Transition from 10% to 99%, 4kHz**



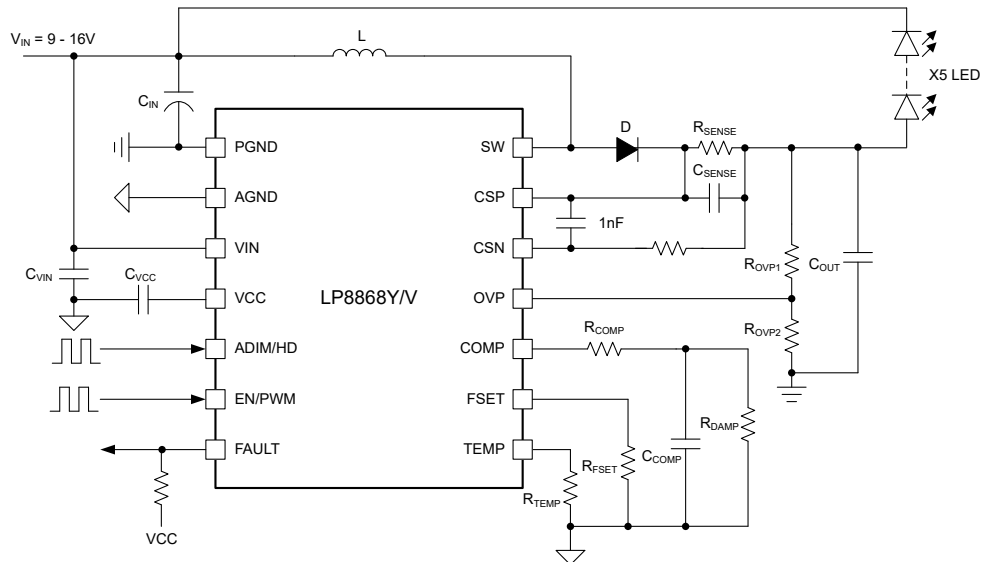
**Figure 8-5. Startup at ADIM = 100%, 500Hz**





### 8.2.2 LP8868YQDMTRQ1 12V Input, 1-A Output, 5-piece LED With Buck-Boost Topology

Figure 8-8 shows a typical application for the LP8868Y in a buck-boost topology. The switching current limit is 5.8 A and the switching current limit restricts the output current.



**Figure 8-8. Typical Application for Buck-Boost Topology with LP8868Y**

#### 8.2.2.1 Design Requirements

For this design example, use the parameters in the following table.

**Table 8-2. Design Parameters**

| PARAMETER           | VALUE    |
|---------------------|----------|
| Input voltage range | 9V – 16V |
| LED string          | 5 LED    |
| Output voltage      | 15V      |
| Switching frequency | 400kHz   |
| Maximum LED current | 1A       |

**Table 8-2. Design Parameters (continued)**

| PARAMETER               | VALUE                           |
|-------------------------|---------------------------------|
| Inductor current ripple | 40% of maximum inductor current |
| Dimming type            | PWM dimming/ADIM dimming        |

### 8.2.2.2 Detailed Design Procedure

#### 8.2.2.2.1 Inductor Selection

For this design, the input voltage is 9V to 16V. The output is 8 white LEDs in series and the inductor current ripple by requirement is less than 40% of maximum LED current. To choose a proper peak-to-peak inductor current ripple, do not violate the low-side FET current limit when the converter works in no-load condition. Avoiding violation requires half of the peak-to-peak inductor current ripple to be lower than that limit. Another consideration is to establish that reasonable inductor core loss and copper loss is caused by the peak-to-peak current ripple. After choosing the peak-to-peak inductor current ripple, use [Equation 13](#) to calculate the recommended value of the inductor L.

$$L = \frac{V_{IN(min)} \times V_{OUT}}{(V_{OUT} + V_{IN(min)}) \times K_{IND} \times I_{L(max)} \times f_{SW}} \quad (13)$$

where

- $K_{IND}$  is a coefficient that represents the amount of inductor ripple current relative to the maximum LED current
- $I_{L(max)}$  is the maximum average inductor current
- $f_{SW}$  is the switching frequency
- $V_{IN(min)}$  is the minimum input voltage
- $V_{OUT}$  is the sum of the voltage across LED load and the voltage across sense resistor

With the chosen inductor value, calculate the actual inductor current ripple using [Equation 14](#).

$$I_{L(ripple)} = \frac{V_{IN(min)} \times V_{OUT}}{(V_{OUT} + V_{IN(min)}) \times L \times f_{SW}} \quad (14)$$

Verify that the design ratings of inductor RMS current and saturation current are greater than the design ratings in the system requirement to confirm that there is no inductor overheat or saturation occurring. During power up, transient conditions or fault conditions, the inductor current may exceed its normal operating current and reach the current limit. Therefore, it is preferred to select a saturation current rating equal to or greater than the converter current limit. The peak-inductor-current and RMS current equations are shown in [Equation 15](#) and [Equation 16](#).

$$I_{L(peak)} = I_{L(max)} + \frac{I_{L(ripple)}}{2} \quad (15)$$

$$I_{L(rms)} = \sqrt{I_{L(max)}^2 + \frac{I_{L(ripple)}^2}{2}} \quad (16)$$

In this design,  $V_{IN(min)} = 9V$ ,  $V_{OUT} = 15V$ ,  $I_{LED} = 1A$ , considering the efficiency as 0.8,  $I_{L(max)} = 2.083A$ ,  $f_{SW} = 400kHz$ , choose  $K_{IND} = 0.4$ , the calculated inductance is  $16.87\mu H$ . A  $22\mu H$  inductor is chosen. With this inductor, the ripple, peak, and rms currents of the inductor are 0.64A, 2.40A, 2.08A, respectively.

#### 8.2.2.2.2 Input Capacitor Selection

An input capacitor is required to reduce the surge current drawn from the input supply and the switching noise coming from the device. Electrolytic capacitors are recommended for energy storage. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of the low ESR and small temperature coefficients. For most applications, the recommendation is to place a  $10\mu F$  capacitor and a  $0.1\mu F$  capacitor from VIN to PGND/AGND to provide high-frequency filtering. Check that the input capacitor voltage rating is greater than the

maximum input voltage. Use Equation 17 to calculate the input ripple voltage, where  $ESR_{CIN}$  is the ESR of input capacitor, and  $K_{DR}$  is the derating coefficient of ceramic capacitance at the applied DC voltage.

$$V_{IN(ripple)} = I_{L(max)} \times \left( \frac{V_{OUT}}{K_{DR} \times C_{IN} \times f_{SW} \times V_{IN(max)}} + ESR_{CIN} \right) \quad (17)$$

In this design, a 33 $\mu$ F, 100V electrolytic capacitor, a 10 $\mu$ F, 100V X7R ceramic capacitor and a 0.1 $\mu$ F, 100V X7R ceramic capacitor are chosen, yielding around 40 mV input ripple voltage.

#### 8.2.2.2.3 Output Capacitor Selection

The output capacitor reduces the high-frequency current ripple through the LED string. Excessive current ripple increases the RMS current in the LED string, therefore increasing the LED temperature.

1. Calculate the total dynamic resistance of the LED string ( $R_{LED}$ ) using the LED manufacturer data sheet.
2. Calculate the required impedance of the output capacitor ( $Z_{OUT}$ ) given the acceptable peak-to-peak ripple current through the LED string,  $I_{LED(ripple)}$ ,  $I_{L(ripple)}$  is the peak-to-peak inductor ripple current as calculated with the selected inductor.
3. Calculate the minimum effective output capacitance required.
4. Increase the output capacitance appropriately due to the derating effect of applied DC voltage. See Equation 18, Equation 19, and Equation 20.

$$R_{LED} = \frac{\Delta V_F}{\Delta I_F} \times \# \text{ of LEDs} \quad (18)$$

$$Z_{COUT} = \frac{R_{LED} \times I_{LED(ripple)}}{I_{L(max)} - I_{LED(ripple)}} \quad (19)$$

$$C_{COUT} = \frac{1}{2\pi \times f_{SW} \times Z_{COUT}} \quad (20)$$

Once the output capacitor is chosen, use Equation 21 to estimate the peak-to-peak ripple current through the LED string.

$$I_{LED(ripple)} = \frac{Z_{COUT} \times I_{L(ripple)}}{Z_{COUT} + R_{LED}} \quad (21)$$

Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of the low ESR and small temperature coefficients. In this design, a 10 $\mu$ F, 50V X7R ceramic capacitor is chosen.

#### 8.2.2.2.4 Sense Resistor Selection

The maximum LED current is 1A at 100% PWM duty and the corresponding  $V_{REF}$  is 200mV. By using Equation 22, the sense resistance is 200m $\Omega$ . Note that the power consumption of the sense resistor is 200mW, requiring enough margin of the resistor power rating in selection.

$$R_{SENSE} = \frac{V_{REF}}{I_{LED\_FS}} \quad (22)$$

In buck-boost topology,  $C_{SENSE}$  is required to achieve the IFD control. Using Equation 23, a 10 $\mu$ F, 50V X7R ceramic capacitor is chosen for  $C_{SENSE}$  to suppress the ac magnitude of sense feedback less than 200mV. A 100 $\Omega$  resistor is recommended at CSN pin to avoid noise injection and increase robustness.

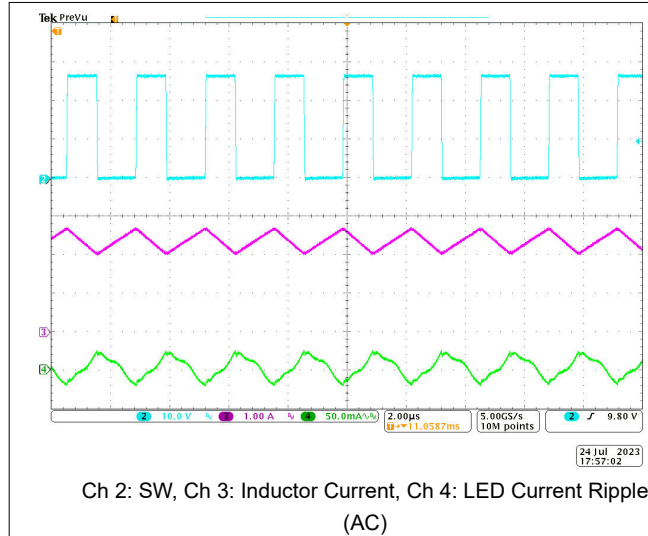
$$C_{SENSE} = \frac{0.25 \times I_{L(max)}}{200mV \times f_{SW}} \quad (23)$$

#### 8.2.2.2.5 Other External Components Selection

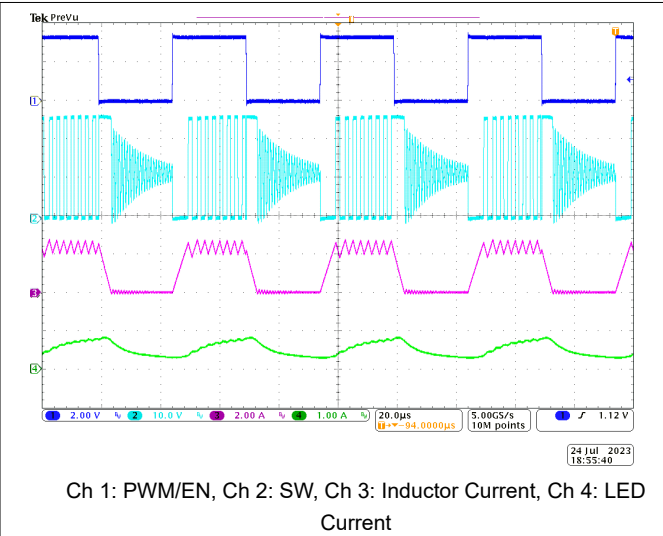
In this design, a 0.1 $\mu$ F, 50V X7R ceramic capacitor is chosen for high-frequency filtering of sense feedback.

For loop stability, the recommendation is to select a 1nF, 10V X7R ceramic capacitor for  $C_{COMP}$  and a 1k $\Omega$  resistor for  $R_{COMP}$ . A 1M $\Omega$  resistor is chosen for  $R_{DAMP}$  to suppress the overshoot current at rising edge of PWM on.

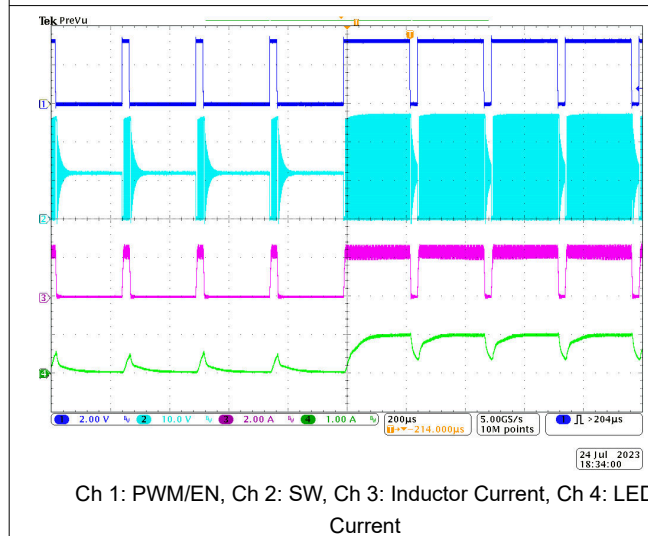
### 8.2.2.3 Application Curves



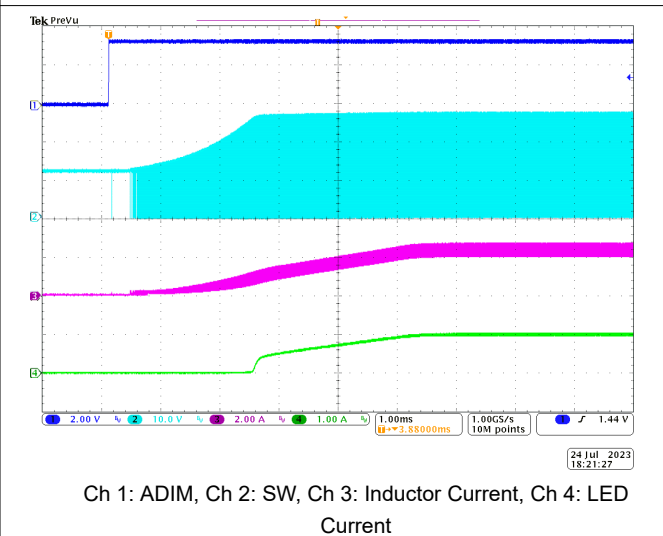
**Figure 8-9. LED Current Ripple at ADIM = 100%, 1kHz and  $F_{SW} = 400kHz$**



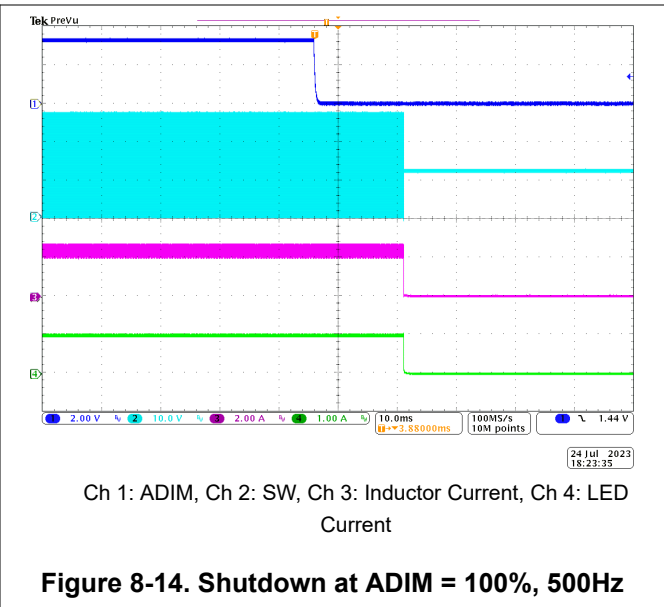
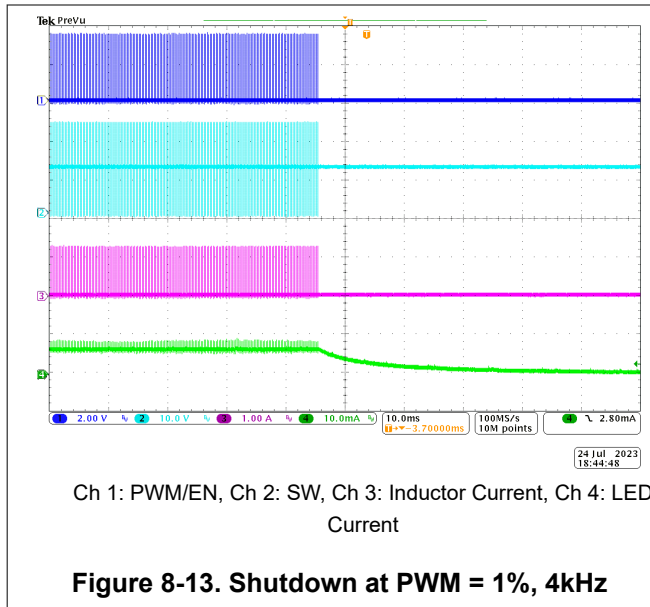
**Figure 8-10. LED Current Ripple at PWM = 50%, 20kHz and  $F_{SW} = 400kHz$**



**Figure 8-11. LED Current Transient for a PWM Transition from 10% to 99%, 4kHz**

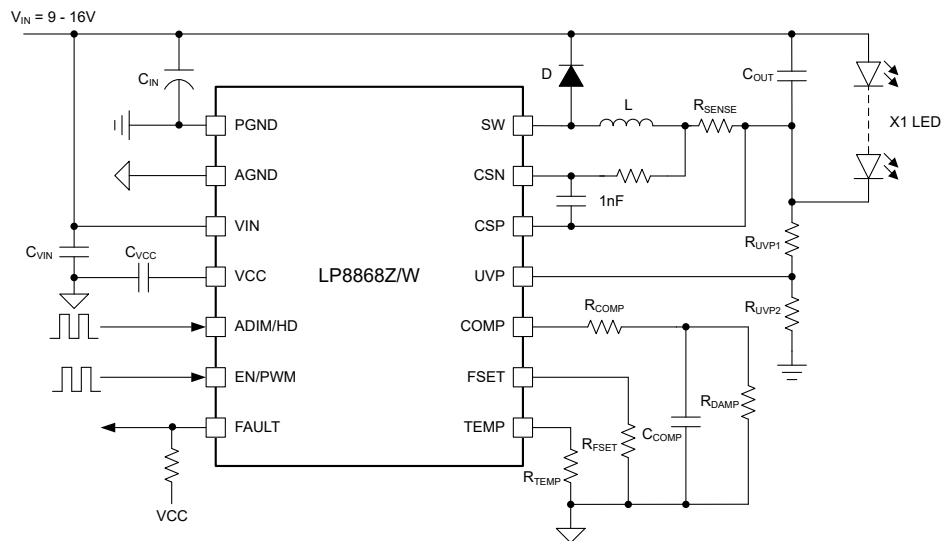


**Figure 8-12. Startup at ADIM = 100%, 500Hz**



### 8.2.3 LP8868ZQDMTRQ1 12V Input, 2A Output, 1-piece LED With Buck Topology

Figure 8-15 shows a typical application for the LP8868Z in a buck topology. The switching current limit is 5.2 A and the output current limit is equal to the limit of switching current limit.



**Figure 8-15. Typical Application for Buck Topology with LP8868Z**

#### 8.2.3.1 Design Requirements

For this design example, use the parameters in the following table.

**Table 8-3. Design Parameters**

| PARAMETER           | VALUE    |
|---------------------|----------|
| Input voltage range | 9V – 16V |
| LED string          | 1 LED    |
| Output voltage      | 3V       |
| Switching frequency | 400kHz   |
| Maximum LED current | 2A       |

**Table 8-3. Design Parameters (continued)**

| PARAMETER               | VALUE                           |
|-------------------------|---------------------------------|
| Inductor current ripple | 40% of maximum inductor current |
| Dimming type            | PWM dimming/ADIM dimming        |

### 8.2.3.2 Detailed Design Procedure

#### 8.2.3.2.1 Inductor Selection

For this design, the input voltage is 9V to 16V. The output is single white LED and the inductor current ripple by requirement is less than 40% of maximum LED current. When choosing a proper peak-to-peak inductor current ripple, do not violate the low-side FET current limit when the converter works in no-load condition. To avoid violation, establish that half of the peak-to-peak inductor current ripple is lower than that limit. Another consideration is to verify the reasonable inductor core loss and copper loss caused by the peak-to-peak current ripple. Once the peak-to-peak inductor current ripple is chosen, use [Equation 24](#) to calculate the recommended value of the inductor L.

$$L = \frac{V_{OUT} \times (V_{IN(max)} - V_{OUT})}{V_{IN(max)} \times K_{IND} \times I_{L(max)} \times f_{SW}} \quad (24)$$

where

- $K_{IND}$  is a coefficient that represents the amount of inductor ripple current relative to the maximum LED current
- $I_{L(max)}$  is the maximum average LED current
- $f_{SW}$  is the switching frequency
- $V_{IN(max)}$  is the maximum input voltage
- $V_{OUT}$  is the sum of the voltage across LED load and the voltage across sense resistor

With the chosen inductor value, calculate the actual inductor current ripple using [Equation 25](#).

$$I_{L(ripple)} = \frac{V_{OUT} \times (V_{IN(max)} - V_{OUT})}{V_{IN(max)} \times L \times f_{SW}} \quad (25)$$

Establish that the design ratings of inductor RMS current and saturation current are greater than the design ratings in the system requirement to ensure that inductor overheat or saturation does not occur. During power up, transient conditions or fault conditions, the inductor current may exceed its normal operating current and reach the current limit. Therefore, the preference is to select a saturation current rating that is equal to or greater than the converter current limit. The peak-inductor-current and RMS current equations are shown in [Equation 26](#) and [Equation 27](#).

$$I_{L(peak)} = I_{L(max)} + \frac{I_{L(ripple)}}{2} \quad (26)$$

$$I_{L(rms)} = \sqrt{I_{L(max)}^2 + \frac{I_{L(ripple)}^2}{2}} \quad (27)$$

In this design,  $V_{IN(max)} = 16V$ ,  $V_{OUT} = 3V$ ,  $I_{LED} = 2A$ , choose  $K_{IND} = 0.4$ , the calculated inductance is 7.6μH. A 10-μH inductor is chosen. With this inductor, the ripple, peak, and rms currents of the inductor are 0.61A, 2.30A, 2A, respectively.

#### 8.2.3.2.2 Input Capacitor Selection

An input capacitor is required to reduce the surge current drawn from the input supply and the switching noise coming from the device. Electrolytic capacitors are recommended for energy storage. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of the low ESR and small temperature coefficients. For most applications, the recommendation is to place a 10μF capacitor along with a 0.1μF capacitor from VIN to PGND/AGND to provide high-frequency filtering. Verify that the input capacitor voltage rating is greater than the maximum input voltage. Use [Equation 28](#) to calculate the input ripple voltage, where  $ESR_{CIN}$  is the ESR of input capacitor, and  $K_{DR}$  is the derating coefficient of ceramic capacitance at the applied DC voltage.

$$V_{IN(ripple)} = I_{L(max)} \times \left( \frac{V_{OUT}}{K_{DR} \times C_{IN} \times f_{SW} \times V_{IN(max)}} + ESR_{CIN} \right) \quad (28)$$

In this design, a 33μF, 100V electrolytic capacitor, two 22μF, 100V X7R ceramic capacitor and a 0.1μF, 100V X7R ceramic capacitor are chosen, yielding approximately 113mV input ripple voltage.

#### 8.2.3.2.3 Output Capacitor Selection

The output capacitor reduces the high-frequency current ripple through the LED string. Excessive current ripple increases the RMS current in the LED string, therefore increasing the LED temperature.

1. Calculate the total dynamic resistance of the LED string ( $R_{LED}$ ) using the LED manufacturer data sheet.
2. Calculate the required impedance of the output capacitor ( $Z_{OUT}$ ) given the acceptable peak-to-peak ripple current through the LED string,  $I_{LED(ripple)}$ .  $I_{L(ripple)}$  is the peak-to-peak inductor ripple current as calculated with the selected inductor.
3. Calculate the minimum effective output capacitance required.
4. Increase the output capacitance appropriately due to the derating effect of applied DC voltage. See [Equation 29](#), [Equation 30](#), and [Equation 31](#).

$$R_{LED} = \frac{\Delta V_F}{\Delta I_F} \times \# \text{ of LEDs} \quad (29)$$

$$Z_{COUT} = \frac{R_{LED} \times I_{LED(ripple)}}{I_{L(max)} - I_{LED(ripple)}} \quad (30)$$

$$C_{COUT} = \frac{1}{2\pi \times f_{SW} \times Z_{COUT}} \quad (31)$$

Once the output capacitor is chosen, use [Equation 32](#) to estimate the peak-to-peak ripple current through the LED string.

$$I_{LED(ripple)} = \frac{Z_{COUT} \times I_{L(ripple)}}{Z_{COUT} + R_{LED}} \quad (32)$$

Ceramic capacitors with X5R or X7R dielectrics are highly recommended because of the low ESR and small temperature coefficients. In this design, a 10μF, 35V X7R ceramic capacitor is chosen.

#### 8.2.3.2.4 Sense Resistor Selection

The maximum LED current is 2A at 100% PWM duty and the corresponding  $V_{REF}$  is 200mV. Use [Equation 33](#) to calculate the sense resistance as 100mΩ. Note that the power consumption of the sense resistor is 400mW, requiring enough margin of the resistor power rating in selection. A 100Ω resistor is recommended at CSN pin to avoid noise injection and increase robustness.

$$R_{SENSE} = \frac{V_{REF}}{I_{LED\_FS}} \quad (33)$$

In buck topology,  $C_{sense}$  is optional to use.

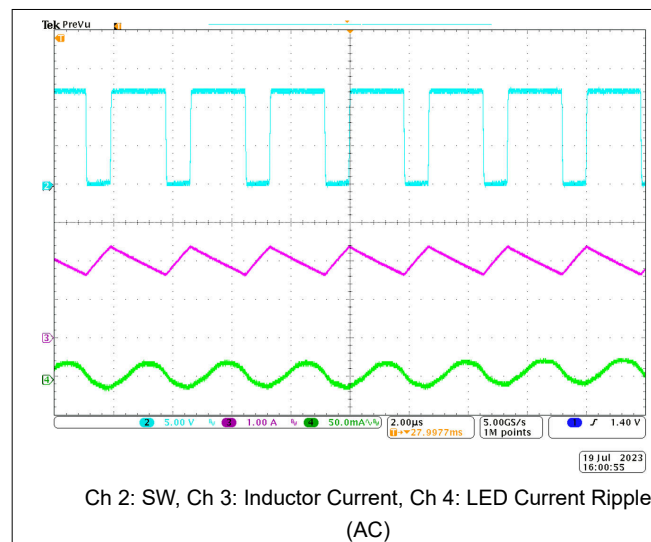
#### 8.2.3.2.5 Other External Components Selection

In this design, a 0.1μF, 50V X7R ceramic capacitor is chosen for high-frequency filtering of sense feedback.

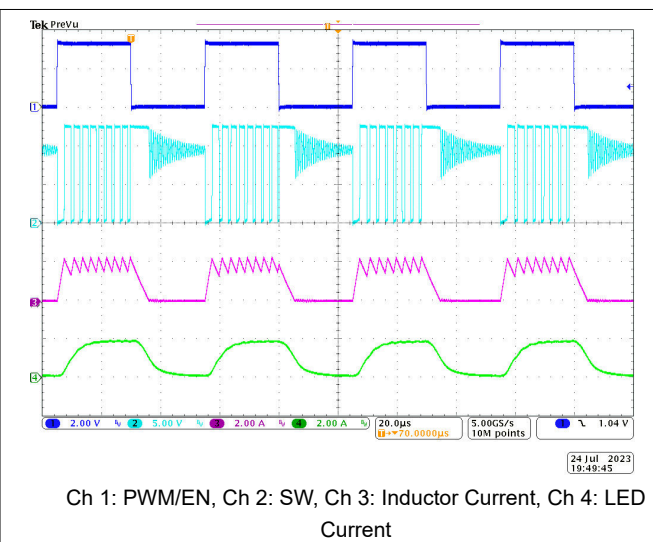
For loop stability, the recommendation is to select a 1nF, 10V X7R ceramic capacitor for  $C_{COMP}$  and a 1kΩ resistor for  $R_{COMP}$ . A 1MΩ resistor is chosen for  $R_{DAMP}$  to suppress the overshoot current at rising edge of PWM on.



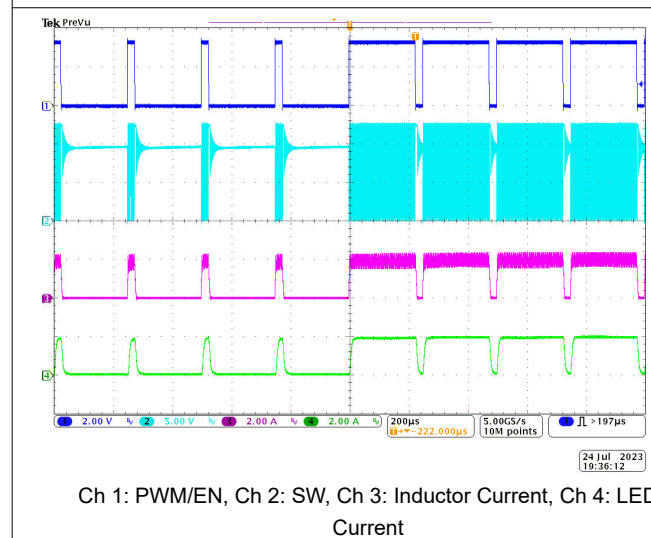
### 8.2.3.3 Application Curves



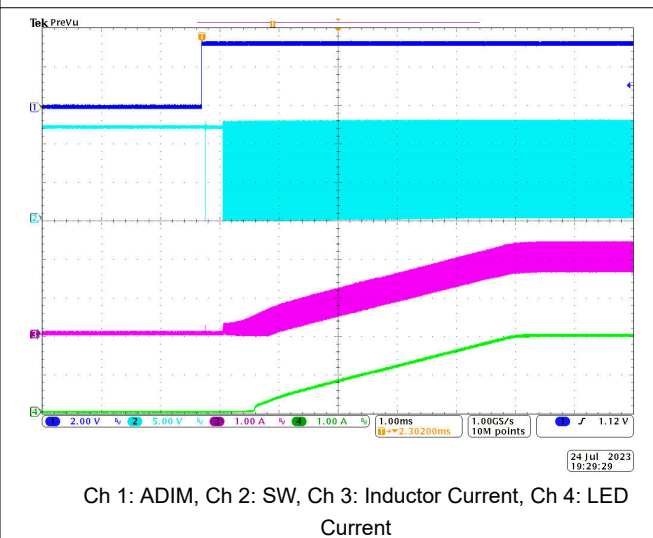
**Figure 8-16. LED Current Ripple at ADIM = 100%, 1kHz and  $F_{SW} = 400kHz$**



**Figure 8-17. LED Current Ripple at PWM = 50%, 20kHz and  $F_{SW} = 400kHz$**

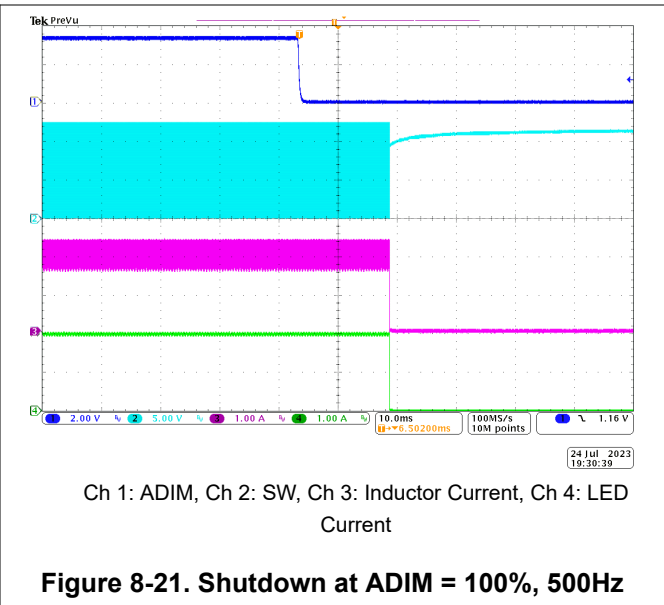
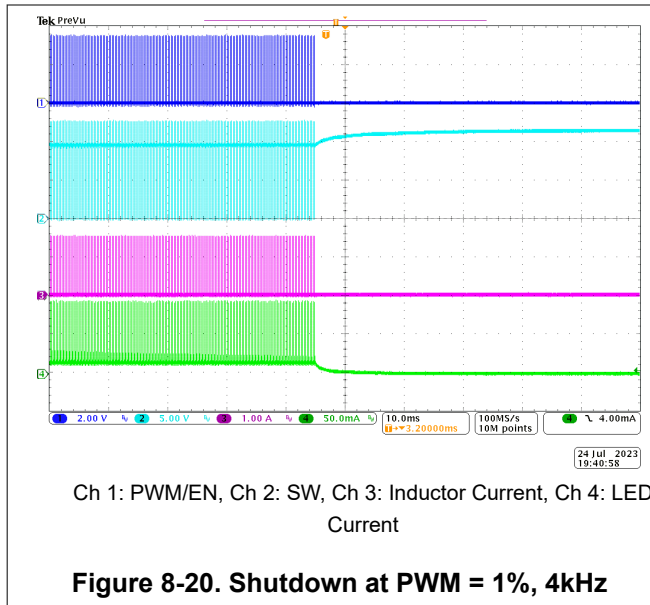


**Figure 8-18. LED Current Transient for a PWM Transition from 10% to 99%, 4kHz**



**Figure 8-19. Startup at ADIM = 100%, 500Hz**





### 8.3 Power Supply Recommendations

The device is designed to operate from an input voltage supply ranging between 4.5V and 65V. Verify that the input supply is well regulated. The device requires an input capacitor to reduce the surge current drawn from the input supply and the switching noise from the device. Ceramic capacitors with X5R or X7R dielectrics are highly recommended because the dielectrics have low ESR and small temperature coefficients. For most applications, a 10µF capacitor is enough.

### 8.4 Layout

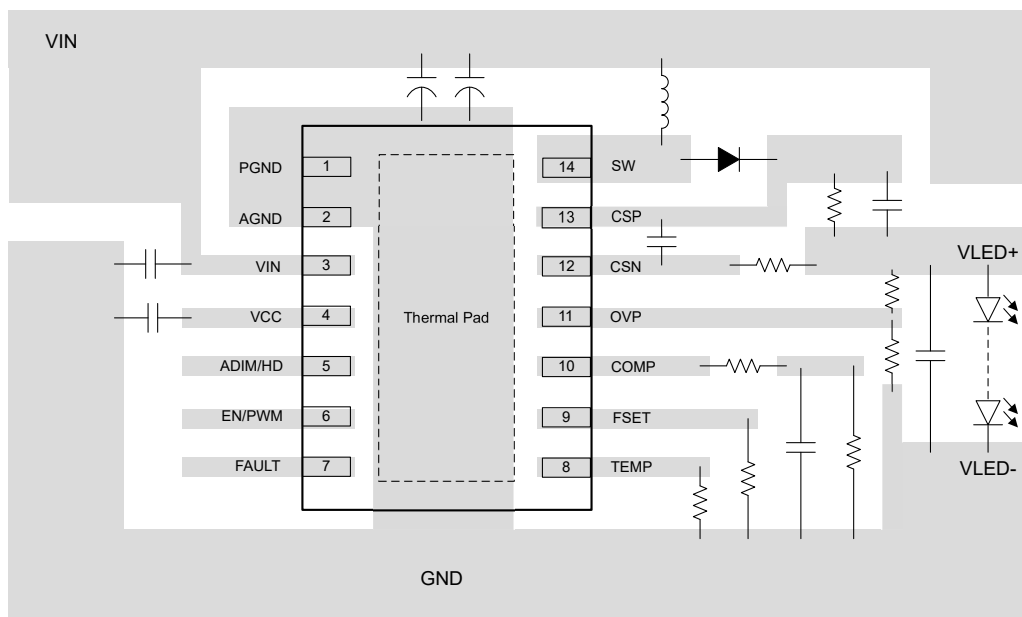
The LP8868-Q1 family requires a proper layout for peak performance. The following section provides guidelines to establish a proper layout.

#### 8.4.1 Layout Guidelines

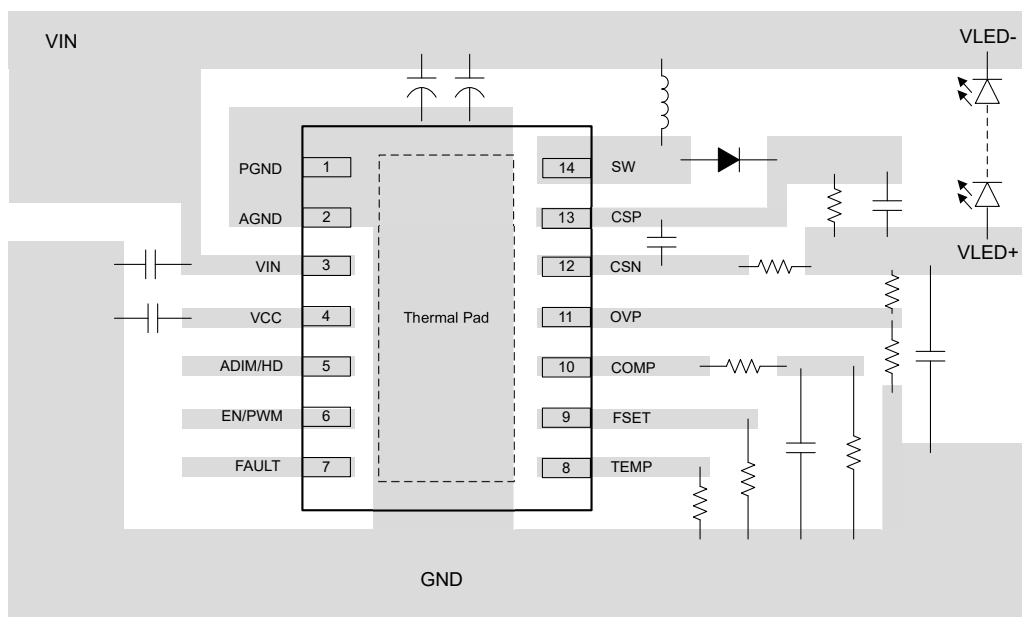
Examples of a proper layout for boost, buck-boost, and buck, topology of the LP8868 family are shown below.

- Creating a large GND plane for good electrical and thermal performance is important.
- Confirm that the IN and GND traces are as wide as possible to reduce trace impedance. Wide traces have the additional advantage of providing excellent heat dissipation.
- Use thermal vias to connect the top-side GND plane to additional printed-circuit board (PCB) layers for heat dissipation and grounding.
- Locate the input capacitors as close as possible to the IN pin and the GND pin.
- Place the VCC capacitor as close as possible to VCC pin to provide stable LDO output voltage.
- Verify that the SW trace remains as short as possible to reduce parasitic inductance and thereby reduce transient voltage spikes. Short SW trace also reduces radiated noise and EMI.
- Do not allow switching current to flow under the device.
- The routing of CSN and CSP traces are recommended to be in parallel and kept as short as possible and placed away from the high-voltage switching trace and the ground shield.
- Place the compensation capacitor as close as possible to COMP pin to prevent oscillation and system instability.

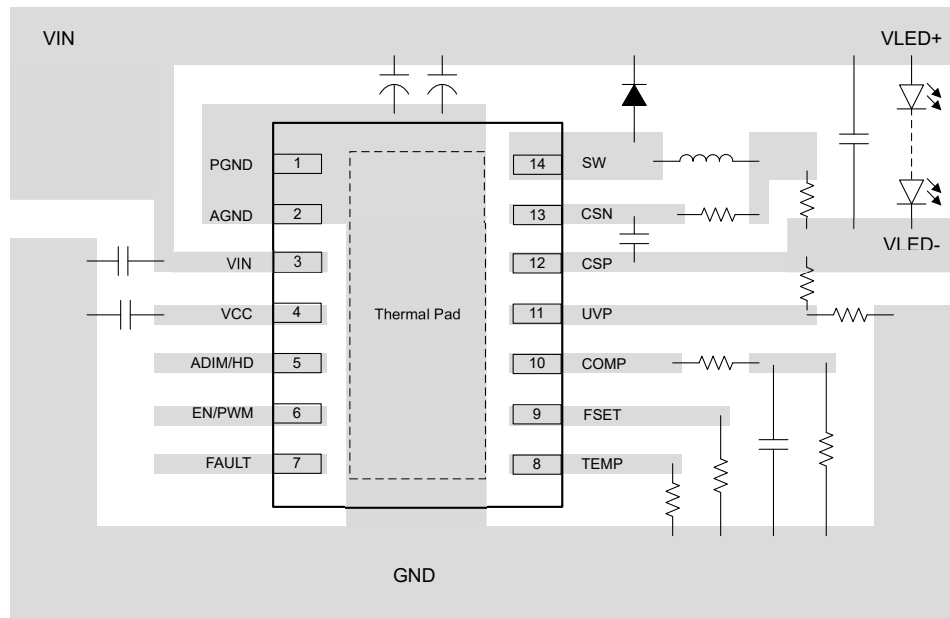
## 8.4.2 Layout Example



**Figure 8-22. Boost Topology Top View Layout Example**



**Figure 8-23. Buck-Boost Topology Top View Layout Example**



**Figure 8-24. Buck Topology Top View Layout Example**

## 9 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

### 9.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 9.2 Support Resources

TI E2E™ [support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

### 9.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.  
All trademarks are the property of their respective owners.

### 9.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

### 9.5 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

## 10 Revision History

| Changes from Revision A (November 2023) to Revision B (Aug 2025)                             | Page |
|----------------------------------------------------------------------------------------------|------|
| • Deleted the Product preview note from the HVSSOP package.....                              | 1    |
| • Updated Typical Boost LED Driver Application Schematic.....                                | 1    |
| • Updated the <i>Comparison Table</i> .....                                                  | 3    |
| • Updated the <i>Pin Configuration and Functions</i> for the HVSOP package.....              | 4    |
| • Changed the Operation temp MAX value from 125 to 150 in Absolute Maximum Rating.....       | 8    |
| • Add the HVSSOP values to the Thermal Information.....                                      | 8    |
| • Updated the HVSSOP Current Limit section of the Electrical Characteristics.....            | 9    |
| • Added text to the <i>Setting LED Current</i> section: "To avoid noise injection ..." ..... | 16   |
| • Changed <a href="#">Figure 8-1</a> .....                                                   | 21   |
| • Changed <a href="#">Equation 2</a> and <a href="#">Equation 3</a> .....                    | 22   |
| • Changed <a href="#">Equation 6</a> .....                                                   | 22   |
| • Changed <a href="#">Figure 8-8</a> .....                                                   | 25   |
| • Changed <a href="#">Equation 13</a> and <a href="#">Equation 14</a> .....                  | 26   |
| • Changed <a href="#">Figure 8-15</a> .....                                                  | 29   |
| • Updated values in the last paragraph in the <i>Inductor Selection</i> .....                | 30   |
| • Updated the Layout Example.....                                                            | 33   |

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**Changes from Revision \* (July 2023) to Revision A (November 2023)**

**Page**

- Added LP8868U-Q1, LP8868V-Q1, LP8868W-Q1 to Production Data..... **1**
-

## 11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most-current data available for the designated s. This data is subject to change without notice and without revision of this document. For browser-based versions of this data sheet, see the left-hand navigation pane.

## PACKAGING INFORMATION

| Orderable part number          | Status<br>(1) | Material type<br>(2) | Package   Pins    | Package qty   Carrier | RoHS<br>(3) | Lead finish/<br>Ball material<br>(4) | MSL rating/<br>Peak reflow<br>(5) | Op temp (°C) | Part marking<br>(6) |
|--------------------------------|---------------|----------------------|-------------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| <a href="#">LP8868UQDMTRQ1</a> | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868U               |
| LP8868UQDMTRQ1.A               | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868U               |
| <a href="#">LP8868VQDMTRQ1</a> | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868V               |
| LP8868VQDMTRQ1.A               | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868V               |
| <a href="#">LP8868WQDMTRQ1</a> | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868W               |
| LP8868WQDMTRQ1.A               | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868W               |
| <a href="#">LP8868XQDGNRQ1</a> | Active        | Production           | HVSSOP (DGN)   12 | 5000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -            | L68X                |
| <a href="#">LP8868XQDMTRQ1</a> | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868X               |
| LP8868XQDMTRQ1.A               | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868X               |
| <a href="#">LP8868YQDGNRQ1</a> | Active        | Production           | HVSSOP (DGN)   12 | 5000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -            | L68Y                |
| <a href="#">LP8868YQDMTRQ1</a> | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868Y               |
| LP8868YQDMTRQ1.A               | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868Y               |
| <a href="#">LP8868ZQDGNRQ1</a> | Active        | Production           | HVSSOP (DGN)   12 | 5000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -            | L68Z                |
| <a href="#">LP8868ZQDMTRQ1</a> | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868Z               |
| LP8868ZQDMTRQ1.A               | Active        | Production           | VSON (DMT)   14   | 3000   LARGE T&R      | Yes         | NIPDAU                               | Level-1-260C-UNLIM                | -40 to 125   | L868Z               |

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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## TAPE AND REEL INFORMATION



\*All dimensions are nominal

| Device         | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| LP8868UQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 330.0              | 12.4               | 3.3     | 4.8     | 1.2     | 8.0     | 12.0   | Q1            |
| LP8868VQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 330.0              | 12.4               | 3.3     | 4.8     | 1.2     | 8.0     | 12.0   | Q1            |
| LP8868WQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 330.0              | 12.4               | 3.3     | 4.8     | 1.2     | 8.0     | 12.0   | Q1            |
| LP8868XQDGNRQ1 | HVSSOP       | DGN             | 12   | 5000 | 330.0              | 12.4               | 5.2     | 4.3     | 1.45    | 8.0     | 12.0   | Q1            |
| LP8868XQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 330.0              | 12.4               | 3.3     | 4.8     | 1.2     | 8.0     | 12.0   | Q1            |
| LP8868YQDGNRQ1 | HVSSOP       | DGN             | 12   | 5000 | 330.0              | 12.4               | 5.2     | 4.3     | 1.45    | 8.0     | 12.0   | Q1            |
| LP8868YQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 330.0              | 12.4               | 3.3     | 4.8     | 1.2     | 8.0     | 12.0   | Q1            |
| LP8868ZQDGNRQ1 | HVSSOP       | DGN             | 12   | 5000 | 330.0              | 12.4               | 5.2     | 4.3     | 1.45    | 8.0     | 12.0   | Q1            |
| LP8868ZQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 330.0              | 12.4               | 3.3     | 4.8     | 1.2     | 8.0     | 12.0   | Q1            |

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

| Device         | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LP8868UQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 367.0       | 367.0      | 35.0        |
| LP8868VQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 367.0       | 367.0      | 35.0        |
| LP8868WQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 367.0       | 367.0      | 35.0        |
| LP8868XQDGNRQ1 | HVSSOP       | DGN             | 12   | 5000 | 353.0       | 353.0      | 32.0        |
| LP8868XQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 367.0       | 367.0      | 35.0        |
| LP8868YQDGNRQ1 | HVSSOP       | DGN             | 12   | 5000 | 353.0       | 353.0      | 32.0        |
| LP8868YQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 367.0       | 367.0      | 35.0        |
| LP8868ZQDGNRQ1 | HVSSOP       | DGN             | 12   | 5000 | 353.0       | 353.0      | 32.0        |
| LP8868ZQDMTRQ1 | VSON         | DMT             | 14   | 3000 | 367.0       | 367.0      | 35.0        |

## GENERIC PACKAGE VIEW

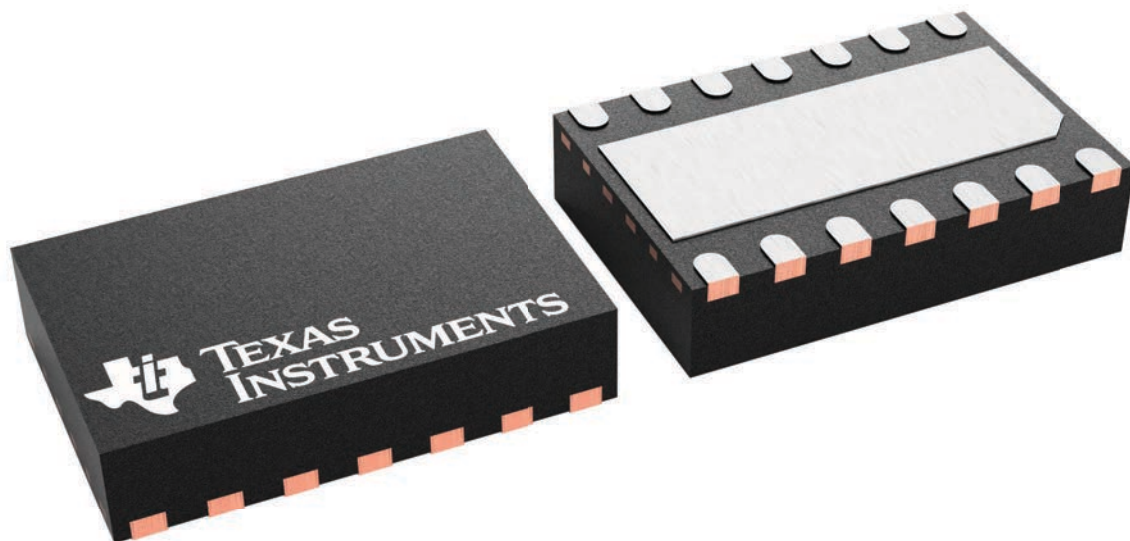
**DMT 14**

**VSON - 0.9 mm max height**

**3 x 4.5, 0.65 mm pitch**

PLASTIC SMALL OUTLINE - NO LEAD

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4225088/A

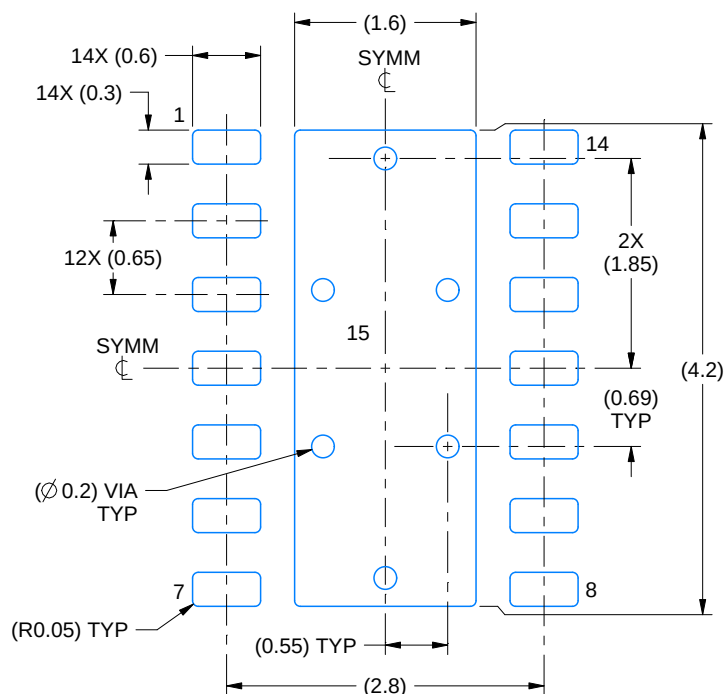


# EXAMPLE BOARD LAYOUT

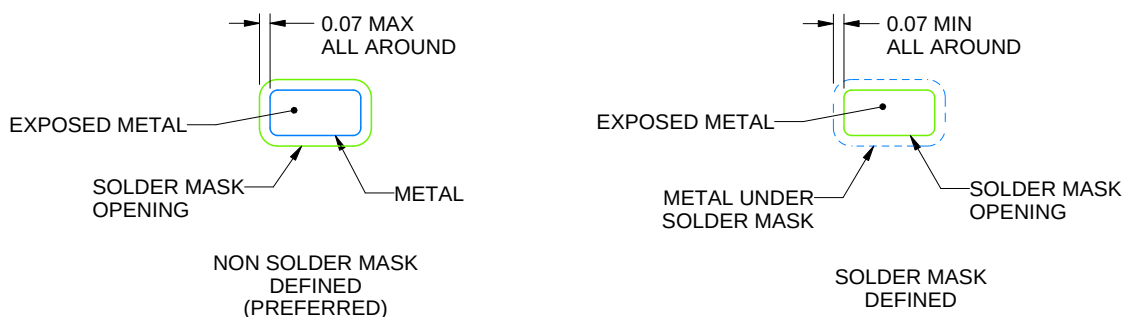
DMT0014B

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

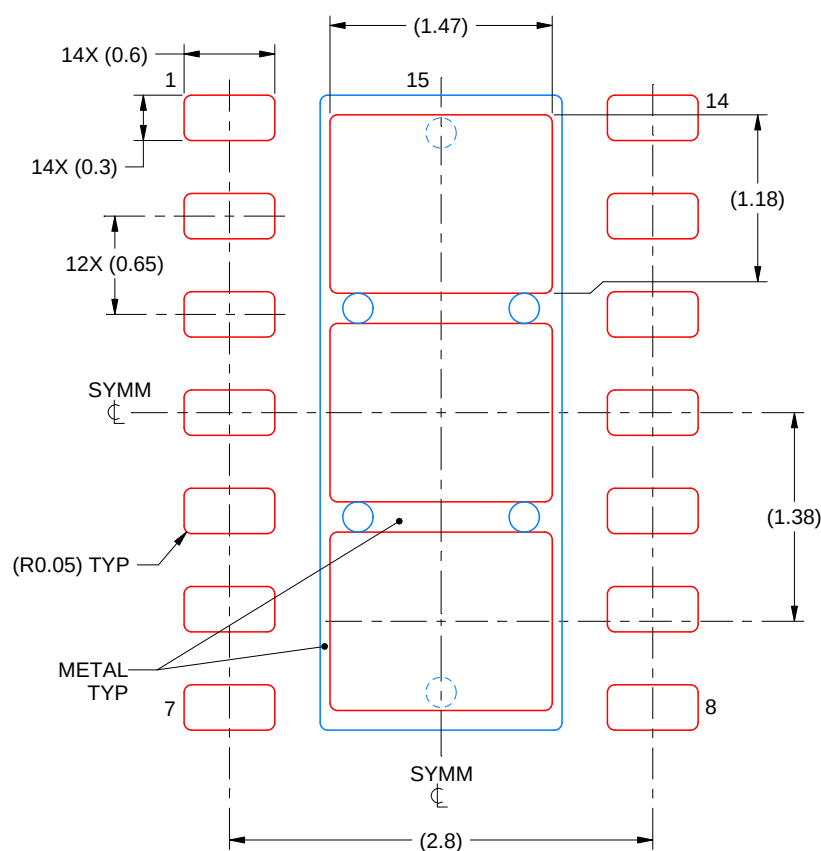
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

DMT0014B

VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 15  
77.4% PRINTED SOLDER COVERAGE BY AREA  
SCALE:20X

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NOTES: (continued)

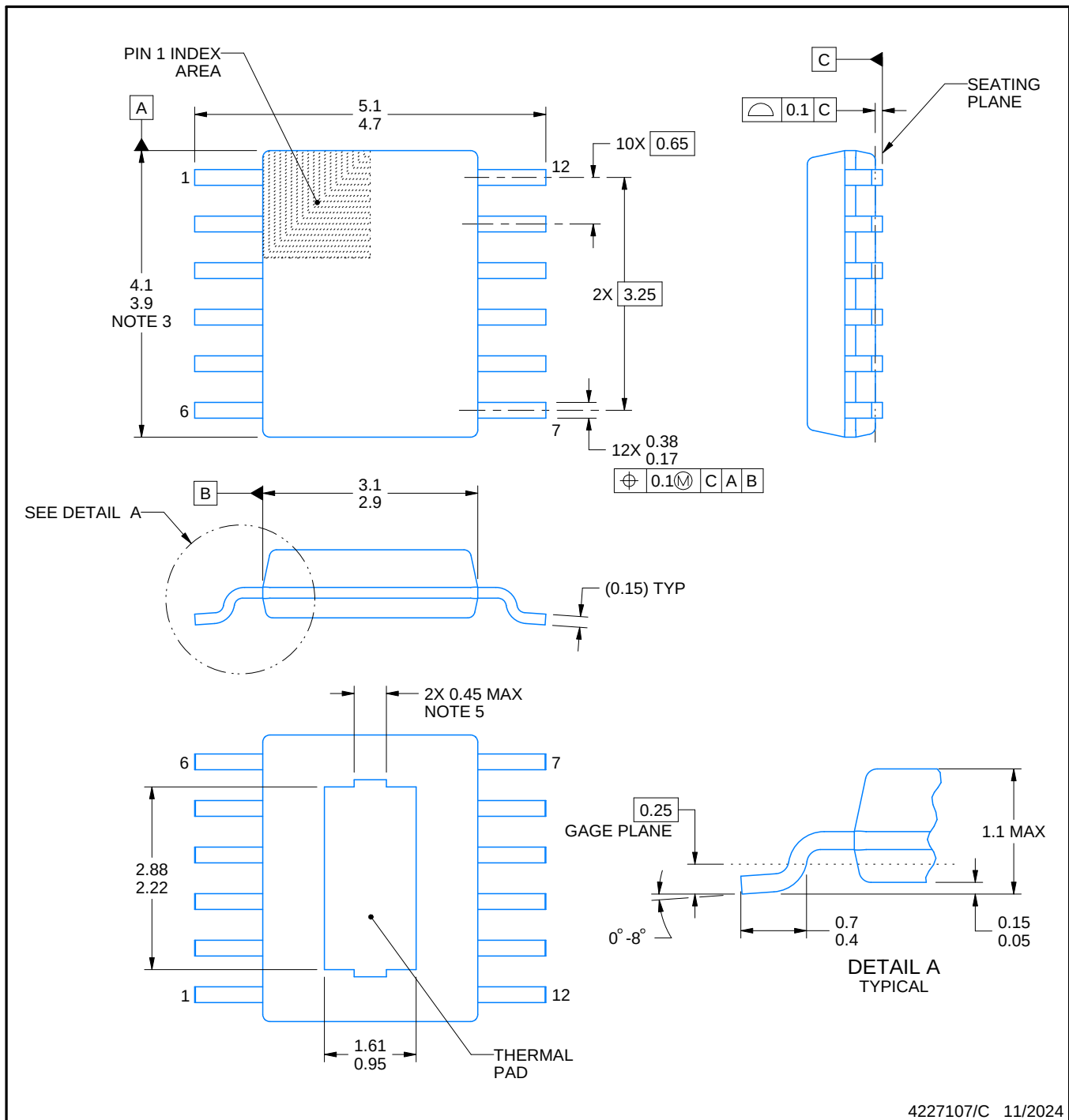
6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.



## PACKAGE OUTLINE

PowerPAD™ HVSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



NOTES:

PowerPAD is a trademark of Texas Instruments.

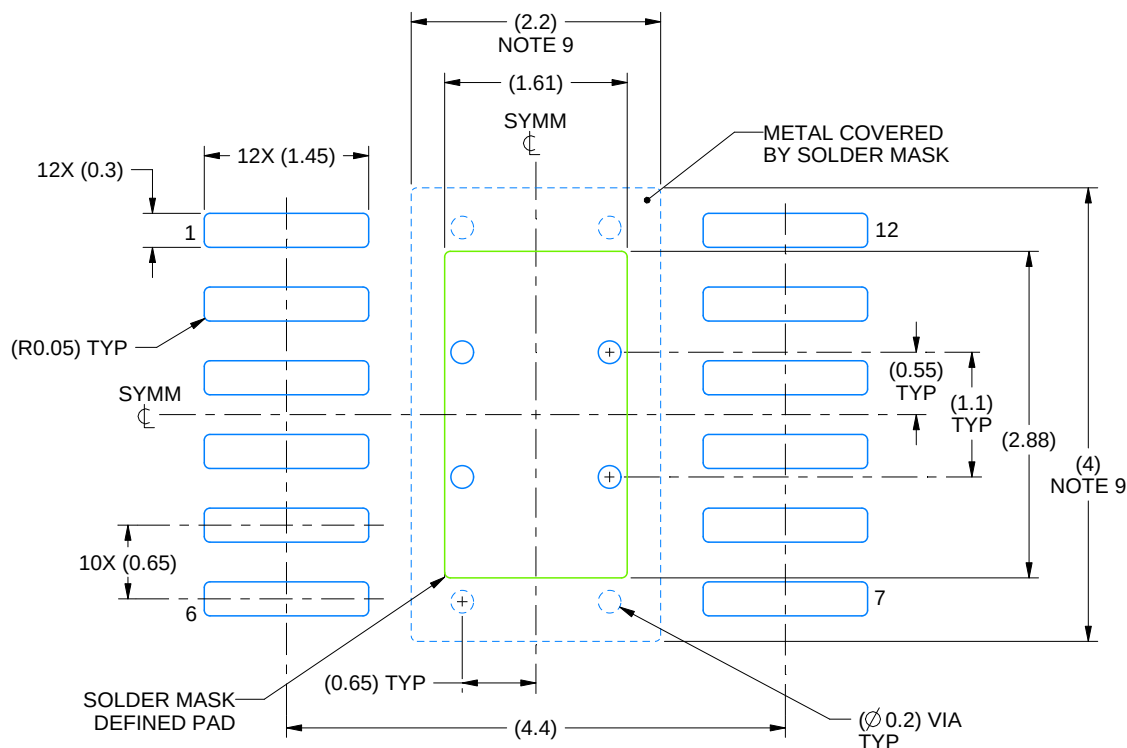
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of September 2020.
5. Features may differ or may not be present.

# EXAMPLE BOARD LAYOUT

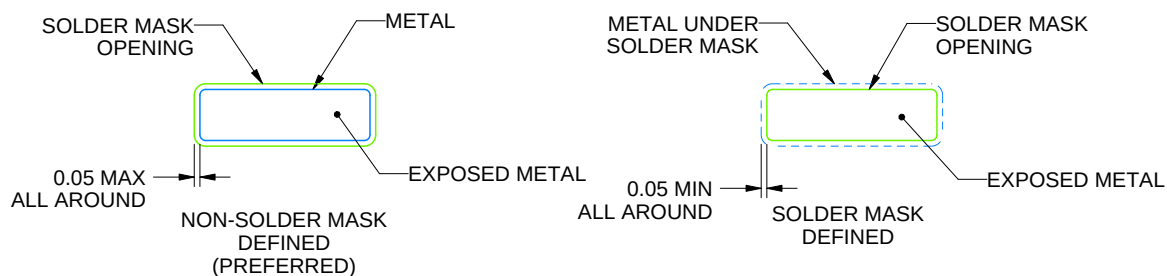
DGN0012A

PowerPAD™ HVSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 15X



SOLDER MASK DETAILS

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 ([www.ti.com/lit/slma002](http://www.ti.com/lit/slma002)) and SLMA004 ([www.ti.com/lit/slma004](http://www.ti.com/lit/slma004)).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

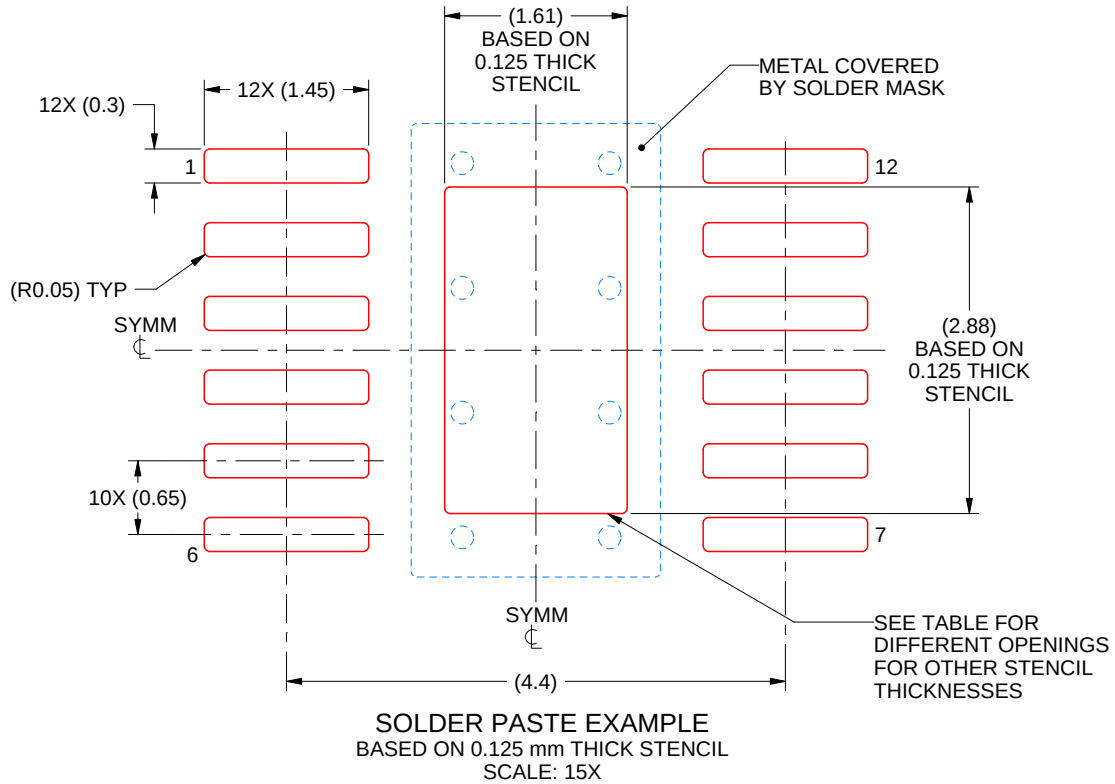


# EXAMPLE STENCIL DESIGN

DGN0012A

PowerPAD™ HVSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



| STENCIL THICKNESS | SOLDER STENCIL OPENING |
|-------------------|------------------------|
| 0.1               | 1.80 X 3.22            |
| 0.125             | 1.61 X 2.88 (SHOWN)    |
| 0.15              | 1.47 X 2.63            |
| 0.175             | 1.36 X 2.43            |

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NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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